VASAVI COLLEGE OF ENGINEERING (AUTONOMOUS)

Accredited by NAAC with 'A++' Grade
Ibrahimbagh, Hyderabad-31
Approved by A.I.C.T.E., New Delhi and
Affiliated to Osmania University, Hyderabad-07

Sponsored by VASAVI ACADEMY OF EDUCATION Hyderabad



SCHEME OF INSTRUCTION AND SYLLABI UNDER CBCS FOR M.E. (ECE)

EMBEDDED SYSTEMS AND VLSI DESIGN (ES&VLSID)

I TO IV SEMESTERS
With effect from 2025-26
(For the batch admitted in 2025-26)

(R-25)



DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING Phones: +91-40-23146040, 23146041

Fax: +91-40-23146090

Institute Vision

Striving for a symbiosis of technological excellence and human values

Institute Mission

To arm young brains with competitive technology and nurture holistic development of the individuals for a better tomorrow

Department Vision

Striving for excellence in teaching, training and research in the areas of Electronics and Communication Engineering

Department Mission

To inculcate a spirit of scientific temper and analytical thinking, and train the students in contemporary technologies in Electronics & Communication Engineering to meet the needs of the industry and society with ethical values.

Program Educational Objectives (PEO)

PG – M.E (ES & VLSID): Embedded Systems and VLSI Design

- **PEO1:** Graduates will be able to design, analyse, and implement systems employing latest techniques and modern tools in the field of Embedded Systems and VLSI Design.
- **PEO2:** Graduates will be able to carry out research independently, write and present a substantial research report.
- **PEO3:** Graduates will be able to demonstrate effective communication skills and leadership qualities with ethical attitudes in broad societal context while working in a multi-disciplinary environment.

Program Outcomes (PO)

PG-M.E (ES & VLSID) : Embedded Systems and VLSI Design : Graduates will have

- **PO1:** An ability to independently carry out research and development work to offer effective engineering solutions and evaluate system level performance.
- **PO2:** An ability to write and present substantial technical reports.
- **PO3:** An ability to demonstrate in depth knowledge for analysing and solving problems in the area of Embedded Systems and VLSI Design.
- **PO4:** An ability to apply appropriate techniques and modern EDA tools to design and conduct advanced experiments and pursue investigations on circuits and system level design.
- **PO5:** An ability to apply engineering and management principles as a member and leader in a team, to manage projects in multi-disciplinary environment with lifelong learning capabilities.

DEPARTMENT OF ECE

SCHEME OF INSTRUCTION AND EXAMINATION (R - 25)

M.E - Embedded Systems and VLSI Design (ES&VLSID) FIRST SEMESTER (2025-2026)

	M.E - ECE (ES&VLSID) I	-Semes	ter					
		Schem	e of Inst	ruction	Scheme of Examination			
Course Code	Name of the Course	Hou	ırs per W	/eek	Duration	Maximun	n Marks	Credits
		L	Т	Р	in Hrs	SEE	CIE	Cre
	THEORY							
P25PC110EC	Professional Core-I: Advanced Embedded System Design	3	-	-	3	60	40	3
P25PC120EC	Professional Core-II: Analog and Digital VLSI Design	3	-	-	3	60	40	3
P25PE1XXEC	Professional Elective - I	3	-	-	3	60	40	3
P25PE1XXEC	Professional Elective - II	3	-	-	3	60	40	3
P25PC140ME	Research Methodology and IPR	2	-	-	3	60	40	2
P25AC110EH	Audit Course-I: English for Research Paper Writing	2	-	-	3	60	40	0
	PRACTICALS							
P25PC111EC	Advanced Embedded Systems Laboratory	4				50	2	
P25PC121EC	Analog and Digital VLSI Design Laboratory	-	-	4	-	-	50	2
	TOTAL	16	-	8	-	360	340	18
	GRAND TOTAL		24			70	0	

DEPARTMENT OF ECE

SCHEME OF INSTRUCTION AND EXAMINATION (R - 25)

M.E Embedded Systems and VLSI Design (ES&VLSID) SECOND SEMESTER (2025-2026)

	M.E - ECE (ES&VLSID) II-Semester							
		Schem	e of Inst	ruction	Scheme of Examination			
Course Code	Name of the Course	Hou	rs per V	/eek	Duration	Maximu	m Marks	Credits
		L	Т	Р	in Hrs	SEE	CIE	Cre
	THEORY							
P25PC210EC	Professional Core-III: Embedded Real Time Operating Systems	3	ı	-	3	60	40	3
P25PC220EC	Professional Core-IV: VLSI Physical Design	3	-	-	3	60	40	3
P25PE2XXEC	P25PE2XXEC Professional Elective - III				3	60	40	3
P25OE2XXXX	Open Elective	3	ı	-	3	60	40	3
P25AC210EH	Audit course-II: Pedagogy Studies	2	-	-	3	60	40	0
	PRACTICALS							
P25PC211EC	Embedded System Applications Laboratory	-	ı	3	-	-	50	2
P25PC221EC	VLSI Physical Design Laboratory	-	-	3	-	-	50	2
P25PW219EC	Mini Project with Seminar	-	ı	2	-	-	50	2
	TOTAL	14	-	8	-	300	350	18
	GRAND TOTAL		22			6!	50	

DEPARTMENT OF ECE

SCHEME OF INSTRUCTION AND EXAMINATION (R - 25)

M.E Embedded Systems and VLSI Design (ES&VLSID) THIRD SEMESTER (2026-2027)

M.E - ECE (ES&VLSID) III-Semester									
		Schen	ne of Instr	uction	Scheme of Examination				
Course Code	Name of the Course	Но	urs per W	eek	Duration	Maximum Marks		dits	
		L	Т	Р	in Hrs	SEE	CIE	Credits	
THEORY									
P25PE3XXEC	Professional Elective – IV	3	ı	ı	3	60	40	3	
P25PE3XXEC	Professional Elective – V	3	-	-	3	60	40	3	
	PR	ACTICAL	S						
P25PW319EC	Dissertation - Phase-I / Internship	-	1	20	1	-	100	10	
	TOTAL	6	1	20	ı	120	180	16	
	GRAND TOTAL		26			3(00		

DEPARTMENT OF ECE

SCHEME OF INSTRUCTION AND EXAMINATION (R - 25)

M.E Embedded Systems and VLSI Design (ES&VLSID) FOURTH SEMESTER (2026-2027)

	M.E - ECE (ES&VLSID) IV-Semester								
			ne of Insti	ruction	Scheme of Examination				
Course Code	Name of the Course	Hours per Week			Duration	Maximum Marks		Credits	
		L	Т	Р	in Hrs	SEE	CIE	Crec	
	PR	ACTICAL	.S						
P25PW419EC	Dissertation – Phase II / Internship	1	-	32	ı	Viva – vo	ce (Grade)	16	
	TOTAL	1	-	32	1	-	1	16	
	GRAND TOTAL		32					·	

DEPARTMENT OF ECE

_			List of Stream Based Prof	fessional Elect	ives (R-25)		
Semester	Professional Elective		ssional Elective Stream 1: Embedded Systems	Professional Elective Stream 2: VLSI System Design			
Sen	Elective	Course Code	Title	Course Code	Title		
	PE-I	P25PE110EC	Programming Languages for Embedded Systems	P25PE120EC	Advanced CMOS Microfabrication		
I	DE 11	P25PE130EC	Advanced Committee Organization	P25PE140EC	FPGA Architectures and Applications		
	PE-II	PZSPEISUEC AUVa	Advanced Computer Organization	P25PE150EC	Scripting Languages		
TT	PE-III	P25PE210EC	Hardware Coffware Co Decign	P25PE220EC	Design Verification using System Verilog		
11	PE-111	PZSPEZIUEC	Hardware-Software Co-Design	P25PE230EC	Static Timing Analysis		
	PE-IV	D2EDE210EC	High Lovel Synthesis	P25PE320EC	Low Power VLSI Design		
ш	I so	riigii Levei Synthesis	P25PE330EC	System on Chip (SoC) Design			
111	PE-V	P25PE340EC	InT Architectures and Applications	P25PE350EC	Physical Design Automation		
	PE-V	rzoreo40EC	IoT Architectures and Applications	P25PE360EC	Design for Testability		

	Audit courses and Open Electives							
S.No.	Course Code	Course Title						
	Audit Course - I							
1	P25AC110EH	English for Research Paper Writing						
2	P25AC120XX	Value Education						
3	P25AC130XX	Stress Management by Yoga						
4	P25AC140XX	Sanskrit for Technical Knowledge						
		Audit Course —II						
1	P25AC210EH	Pedagogy Studies						
2	P25AC220XX	Personality Development through Life Enlightenment Skills.						
3	P25AC230XX	Constitution of India						
4	P25AC240XX	Disaster Management						
		Open Electives						
1	P250E210XX	Business Analytics						
2	P250E220XX	Industrial Safety						
3	P250E230XX	Operations Research						
4	P250E240XX	Cost Management of Engineering Projects						
5	P250E250XX	Composite Materials						
6	P250E260XX	Waste to Energy						
7	P250E270XX	Fundamentals of Python Programming						

Syllabus for M.E. ECE (ES & VLSI Design) I - SEMESTER

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Advanced Embedded System Design

Professional Core - I

SYLLABUS FOR M.E. ECE (ES&VLSID) - I SEMESTER

L:T:P (Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P25PC110EC
Credits: 3	CIE Marks: 40	Duration of SEE : 3 Hours

COURSE OBJECTIVES	COURSE OUTCOMES
Define and Classify an Embedded System along with design issues.	On completion of the course, students will be able to 1. Define, Classify and Analyze embedded
 Justify the philosophy of ARM core as CPU in SoC designs. Demonstrate ARM ISA Assembly usage for data processing. 	system product design with IC Technology. 2. Analyze ARM IP Core usage in design with its programming model and registers. 3. Implement ARM assembly construct for Cortex M4
4. Implement different I/O interfacing drivers for Cortex M4 MCU in C.	4. Design device drivers in embedded-C for Cortex M4 to interface different I/O.5. Propose hardware software codesign issues along with debugging techniques.

CO-PO Mapping

CO	PO1	PO2	PO3	PO4	PO5
CO1	1	2	3	2	-
CO2	1	2	3	2	-
CO3	1	2	3	2	-
CO4	1	2	3	2	-
CO5	1	2	3	2	-

UNIT - I:

Embedded Systems Design Introduction: Definition of Embedded System; Examples; Classifications based on Cost and Size; Hard Real Time Systems, Soft Real Time Systems, Life Cycle of Embedded System. Issues of Time-to-Market; Selection of CPU, memories and I/O; RISC Vs CISC; Design Metric.

UNIT - II:

Embedded systems using ARM: Nomenclature; Core Architecture; Introduction to AMBA Bus; Registers – CPSR, SPSR, Modes; Thumb Mode;

Exceptions, OBD using JTAG; ARM family variants: ARM7, ARM9 and Cortex Cores and comparisons.

UNIT - III:

ARM CortexM4 architecture and Programming: Introduction; Cortex CPU Block diagram; ARM Assembly Level Programming: Load and Store instructions; Data Formats and Directives; Addressing Modes; ALU instructions, Branching instructions.

UNIT - IV:

ARM [STM32F4xx] Real World Interfacing: Interfacing of switches, LEDs; Seven Segment Display; Matrix Keypad interface; LCD interfacing; DC Motor, Stepper Motor interfacing designs.

UNIT - V:

Hardware Software Codesign: Co-Design with a case study of Adaptive Cruise Control Design. Software architectures—Round Robin, RR with interrupts, Functional Queue.

Debugging: Host, Target, Big-Endian, Little-Endian ISA. Debugging methods in S/W & H/W.

Learning Resources:

- 1. STM32 ARM Programming for Embedded Systems, Muhammad Ali Mazidi, Shujen Chen, Eshragh Ghaemi ISBN: 978-099-792-5944, 2018
- Muhammad Tahir and Kashif Javed, "ARM® Microprocessor Systems: Cortex®-M Architecture, Programming, and Interfacing", CRC Press, © 2017 by Taylor & Francis Group, LLC
- 3. NPTEL-"Embedded System Design Using ARM", https://archive.nptel.ac.in/courses/106/105/106105193/

The	The break-up of CIE: Internal Tests + Assignments + Quizzes						
1.	No. of Internal Tests	:	2	Max. Marks for each Internal Tests	:	30	
2.	No. of Assignments	:	3	Max. Marks for each Assignment	:	5	
3.	No. of Quizzes	:	3	Max. Marks for each Quiz Test	:	5	

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Analog and Digital VLSI Design

Professional Core - II SYLLABUS FOR M.E. ECE (ES&VLSID) - I SEMESTER

L:T:P (Hrs./week) : 3:0:0	SEE Marks: 60	Course Code: P25PC120EC
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

	COURSE OBJECTIVES	COURSE OUTCOMES
1.	Analyse the effect of sizing the devices of CMOS circuits and its performance in terms of logical and electrical efforts.	On completion of the course, students will be able to 1. Design MOS transistor circuits. 2. Know the Physical design flow and
2.	Introduce the principles of analog circuits and apply the techniques for the design of analog integrated	different modelling design. 3. Design sequential circuits at higher level.
	circuit	4. Design analog circuits like single stage and differential amplifiers.
		5. Analyze frequency response of active circuits.

CO-PO Mapping

CO	PO1	PO2	PO3	PO4	PO5
CO1	2		1		
CO2	1		1		
CO3	2		3		
CO4	2		3		
CO5	2		2		

UNIT - I:

Review: Basic MOS structure and its static behavior, Quality metrics of a digital design: Cost, Functionality, Robustness, Power, Delay, Wire delay models. Physical design flow: Floor planning, Placement, Routing, CTS, Power analysis and IR drop estimation-static and dynamic, ESD protection-human body model.

UNIT - II:

Inverter: Static CMOS inverter, Switching threshold and noise margin concepts and their evaluation, Dynamic behavior, Power consumption. Combinational logic: Static CMOS design, Logic effort, Ratioed logic, Pass transistor logic, Dynamic logic, Speed and power dissipation in dynamic logic, Cascading dynamic gates, transmission gate logic.

UNIT - III:

Sequential logic: Static latches and registers, Bi-stability principle, MUX based latches, Static SR flip-flops, Master-slave edge-triggered register, Dynamic latches and registers, Concept of pipelining, Pulse registers, and Non-bistable sequential circuit.

Giga-scale dilemma, Short channel effects, High–k, Metal Gate Technology, FinFET, and TFET.

UNIT - IV:

Single Stage Amplifier: CS stage with resistance load, Diode connected load, Current source load, Triode load, CS stage with source degeneration, Source follower, Common gate stage, Cascode stage, Choice of device models. Differential Amplifiers: Basic differential pair, Common mode response, Differential pair with MOS loads, Gilbert cell.

UNIT - V:

Current mirrors: Basic current mirrors, Applications of current Sources, Sizing issues, Cascode mirrors, Active current mirrors.

Learning References:

- 1. J P Rabaey, A P Chandrakasan, B Nikolic, "Digital Integrated circuits: A design perspective", Prentice Hall electronics and VLSI series, 2nd Edition.
- Baker, Li, Boyce, "CMOS Circuit Design, Layout, and Simulation", Wiley, 2nd Edition.
- 3. Behzad Razavi, "Design of Analog CMOS Integrated Circuits", TMH, 2007.
- 4. Phillip E. Allen and Douglas R. Holberg, "CMOS Analog Circuit Design", Oxford, 3rd Edition.
- 5. Kang, S. and Leblebici, Y., "CMOS Digital Integrated Circuits, Analysis and Design", TMH, 3rdEdition.
- 6. Pucknell, D.A. and Eshraghian, K., "Basic VLSI Design", PHI, 3rd Edition.

The	The break-up of CIE: Internal Tests + Assignments + Quizzes					
1.	No. of Internal Tests	: 2 Max. Marks for each Internal Tests	:	30		
2.	No. of Assignments	: 3 Max. Marks for each Assignment	:	5		
3.	No. of Quizzes	: 3 Max. Marks for each Quiz Test	:	5		

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DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Programming Languages for Embedded Systems

Professional Elective - I

SYLLABUS FOR M.E. ECE (ES&VLSID) - I SEMESTER

L:T:P (Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P25PE110EC
Credits: 3	CIE Marks: 40	Duration of SEE : 3 Hours

COURSE OBJECTIVES	COURSE OUTCOMES
 To impart knowledge on embedded C To understand algorithms in C++. To Develops CPP programming. To understand Inheritance and overloading To acquire the knowledge about templates concepts. 	 On completion of the course, students will be able to Write an embedded C application of moderate complexity. Develop and analyze algorithms in C++. Design embedded software using object oriented programming principles. Apply the concept of generic programming for embedded systems. Write exception handlers for embedded software.

CO-PO Mapping

CO	PO1	PO2	PO3	PO4	PO5
CO1			3	2	
CO2			3	3	
CO3			2	3	
CO4			2	2	
CO5			3	2	

UNIT – I

Embedded 'C' Programming

- Bitwise operations, Dynamic memory allocation, OS services
- Linked stack and queue, Sparse matrices, Binary tree
- Interrupt handling in C, Code optimization issues
- Writing LCD drives, LED drivers, Drivers for serial port communication
- Embedded Software Development Cycle and Methods (Waterfall, Agile)

UNIT - II

Object Oriented Programming - Introduction to procedural, modular, objectoriented and generic programming techniques, Limitations of procedural programming, objects, classes, data members, methods, data encapsulation, data abstraction and information hiding, inheritance, polymorphism

UNIT - III

CPP Programming: 'cin', 'cout', formatting and I/O manipulators, new and delete operators, Defining a class, data members and methods, 'this' pointer, constructors, destructors, friend function, dynamic memory allocation

UNIT - IV

Overloading and Inheritance: Need of operator overloading, overloading the assignment, overloading using friends, type conversions, single inheritance, base and derived classes, friend classes, types of inheritance, hybrid inheritance, multiple inheritance, virtual base class, polymorphism, virtual functions,

UNIT - V

Templates: Function template and class template, member function templates and template arguments, Exception Handling: syntax for exception handling code: try-catch- throw, Multiple Exceptions.

Learning Resources:

- Michael J. Pont, "Embedded C", Pearson Education, 2nd Edition, 2008 1.
- Randal L. Schwartz, "Learning Perl", O'Reilly Publications, 6th Edition 2011 2.
- 3.
- A. Michael Berman, "Data structures via C++", Oxford University Press, 2002 Robert Sedgewick, "Algorithms in C++", Addison Wesley Publishing Company, 4. 1999
- 5. Abraham Silberschatz, Peter B, Greg Gagne, "Operating System Concepts", John Willey & Sons, 2005

The	e break-up of CIE: Inte	erna	al Te	ests + Assignments + Quizzes		
1.	No. of Internal Tests	:	2	Max. Marks for each Internal Tests	:	30
2.	No. of Assignments	:	3	Max. Marks for each Assignment	:	5
3.	No. of Quizzes		3	Max. Marks for each Ouiz Test		5

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DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Advanced CMOS Microfabrication

(Professional Elective-I)

SYLLABUS FOR M.E. ECE (ES&VLSID) - I SEMESTER

L:T:P (Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P25PE120EC
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

	COURSE OBJECTIVES	COURSE OUTCOMES					
	To introduce the fundamental concepts of semiconductor physics and materials essential for IC fabrication.	On completion of the course, students will be able to 1. Understand fundamental semiconductor					
2.	To familiarize with thermal oxidation and thin-film deposition processes used in CMOS technology.	properties, carrier dynamics, and materials relevant to microfabrication. 2. Apply oxidation and thin-film deposition					
3.	To understand key microfabrication steps such as diffusion, ion implantation, photolithography, and etching.	techniques used in CMOS process technology. 3. Demonstrate knowledge of diffusion, ion					
4.	To explore the complete CMOS and FinFET fabrication processes and address associated technological challenges.	implantation, photolithography, and etching in microfabrication.4. Analyze CMOS and FinFET fabrication flows, including advanced techniques					
5.	To impart knowledge of characterization methods used to analyze semiconductor material and device properties.	like salicidation and damascene processing. 5. Utilize electrical and physical characterization tools for evaluating semiconductor devices and materials.					
CC	CO-PO/PSO Mapping						

CO-PO	PSU	марр	ıng

CO	PO1	PO2	PO3	PO4	PO5
CO1	2		2		
CO2	3		3	2	
CO3	3		3	2	
CO4	3		3	2	
CO5	2		2	3	

UNIT-I:

FUNDAMENTALS OF SEMICONDUCTORS: Crystal lattices, Bulk crystal Growth, Epitaxial Growth, Bonding forces and energy bands in solids, Charge carriers in semiconductors, Carrier concentrations, Drift of carriers in Electric and Magnetic Fields, Hall effect, Fermi level at equilibrium, Intrinsic vs Extrinsic semiconductors, Excess carriers in semiconductors, Diffusion and recombination, Diffusion length, Properties of Silicon and compounds, Gallium Arsenide, Metals used in IC fabrication.

UNIT-II:

FABRICATION TECHNIQUES I: Top-Down and Bottom-Up Approach, Wafer Cleaning, Silicon Oxidation Techniques: Thermal Oxidation process, Deal-Groove model of oxidation, types of oxidation techniques, growth mechanism, factors affecting the growth mechanisms, dry & wet oxidation. Film deposition: Chemical Vapour deposition, Physical Vapour deposition, Polysilicon deposition, Dielectric deposition.

UNIT-III:

FABRICATION TECHNIQUES II: Diffusion: Basic diffusion process, Extrinsic diffusion, Lateral diffusion, Ion Implantation: Range of Implanted Ions, Implant damage and Annealing, Tilt- Angle Ion Implantation. Photolithography: Optical lithography, Photoresists, Masks, Pattern Transfer. Etching: Wet Chemical Etching, Dry Etching, Isotropic and Anisotropic etching.

UNIT-IV:

CMOS FinFET: Basic MOS Capacitor, MOSFET fabrication process, CMOS Technology, Challenges of STI versus LOCOS, FinFET architecture, Gate first versus gate last, contact resistance issues of simple metal-silicon contact, metal silicides, salicidation, evolution from Ti to Co to Ni silicide, Damascene and dual-Damascene process.

UNIT-V:

CHARACTERIZATION TECHNIQUES: Resistivity: Two-Point versus Four-Point Probe, Carrier and doping density: Capacitance-Voltage (C-V) characterization, Current-Voltage characterization, Optical characterization: Introduction to Ellipsometry, Scanning probe microscopy: SEM, TEM and AFM.

Learning Resources:

- Ben Streetman, Sanjay Banerjee Solid State Electronic Devices-Prentice Hall (2006)
- 2. Jan M. Rabaey, Anantha Chandrakasan, Digital Integrated Circuits: A Design Perspective, Prentice Hall of India, 2016.
- 3. Tai-Ran Hsu MEMS & Microsystems Design and Manufacture-Tata McGraw-Hill Education (2002).
- 4. Weste, Neil H E_Harris, David Money CMOS VLSI Design_ A Circuits and Systems Perspective-Addison-Wesley (2010).
- 5. Stephen D. Senturia, Microsystem design, Springer (India), 2006.

The	he break-up of CIE: Internal Tests + Assignments + Quizzes						
1.	No. of Internal Tests	: 2	Max. Marks for each Internal Test	: 30			
2.	No. of Assignments	: 3	Max. Marks for each Assignment	: 5			
3.	No. of Ouizzes	: 3	Max. Marks for each Ouiz Test	: 5			

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Advanced Computer Organization

Professional Elective - II
SYLLABUS FOR M.E. ECE (ES&VLSID) - I SEMESTER

L:T:P (Hrs./week) : 3:0:0	SEE Marks: 60	Course Code: P25PE130EC
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

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COURSE OBJECTIVES	COURSE OUTCOMES				
By the end of this course, students	On completion of the course, students				
should be able to	will be able to				
1. Understand RISC-V as an open ISA,	1. Compare RISC-V's open-standard				
comparing its modularity and	advantages with ARM/x86 and justify				
extensibility with proprietary	its use cases in modern computing.				
architectures (ARM, x86).	2. Write and debug RISC-V programs				
2. Analyze RISC-V's instruction formats,	using base and extended ISAs				
base and standard extensions.	3. Optimize RISC-V pipeline				
3. Design pipelined RISC-V systems,	performance by mitigating hazards				
addressing hazards, branch penalties,	and implementing superscalar				
and superscalar techniques for	techniques.				
performance optimization.	4. Configure RISC-V's privileged modes				
4. Evaluate privileged ISA features and	for interrupt handling.				
custom extensions for tailored	5. Design scalable RISC-V systems				
hardware/software solutions.	leveraging parallelism (multicore,				
5. Apply parallel computing concepts					
(ILP, multiprocessors, SIMD) to RISC-	performance applications.				
V-based systems, including shared					
memory and vector processors.					
CO-PO Manning					

CO-PO Mapping

CO	PO1	PO2	PO3	PO4	PO5
CO1	2	1	3		
CO2	2	1	3	2	
CO3	3	1	3	2	
CO4	3	1	3	1	
CO5	3	1	3		
CO6	2	1	3		

UNIT-I: Introduction to RISC-V

Motivation: Why RISC-V?, Open ISA vs. Proprietary ISAs (ARM, x86), Key Features of RISC-V like Modularity, Extensibility, etc., Open ISA vs. Proprietary ISAs (ARM, x86), Comparison with Other Architectures: ARM vs. RISC-V vs. x86

UNIT-II: RISC-V ISA Basics

Instruction Formats & Types: R-Type, I-Type, S-Type, B-Type, U-Type, J-Type, Base Integer ISA (RV32I, RV64I), Registers (x0-x31, Zero Register), Arithmetic, Logical, and Control Instructions, Memory Access (Load/Store)

UNIT-III: Advanced RISC-V ISA Extensions

Standard Extensions: M (Multiplication & Division), A (Atomic Operations), F (Single-Precision Floating Point), D (Double-Precision Floating Point), C (Compressed Instructions), Privileged ISA (Supervisor & Machine Mode): CSRs (Control & Status Registers), Exceptions, Interrupts, and Traps, Custom Extensions: How to Define Custom Instructions

UNIT-IV: Pipelining Techniques

Super Scalar techniques, Super scalar and super pipeline design, Basic performance issues in pipelining, Pipeline hazards, Reducing pipeline branch penalties.

UNIT-V: Parallel Computer Systems

Instruction Level Parallelism (ILP), Multi-processors – Characteristics, Symmetric and Distributive Shared Memory Architecture, Vector Processors, SIMD computers and Super computers

Learning Resources:

- 1. The RISC-V Reader: An Open Architecture Atlas, David Patterson, Andrew Waterman, Strawberry Canyon LLC.
- 2. John L. Hennessy and David A. Patterson, Computer Architecture A quantitative Approach, 3rd Edition, Elsevier, 2005.
- 3. Computer Architecture and Parallel Processing Kai Hwang, Faye A.Brigs., MC Graw Hill.
- 4. "Programming with RISC-V", Steve Rhoads

The	The break-up of CIE: Internal Tests + Assignments + Quizzes					
1.	No. of Internal Tests	:[2	Max. Marks for each Internal Tests	:	30
2.	No. of Assignments	:[3	Max. Marks for each Assignment	:	5
3.	No. of Quizzes	:	3	Max. Marks for each Quiz Test	:	5

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DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

FPGA Architectures and Applications

Professional Elective - II SYLLABUS FOR M.E. ECE (ES&VLSID) - I SEMESTER

L:T:P (Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P25PE140EC
Credits: 3	CIE Marks: 40	Duration of SEE : 3 Hours

COURSE OBJECTIVES	COURSE OUTCOMES
By the end of this course, students will be able to:	After completing this course, students will be able to:
1. Understand the architecture, programming methods, and applications of Simple Programmable Logic Devices (SPLDs) like PROM, PLA, and PAL.	
2. Apply Shannon's expansion theorem and logic synthesis techniques to realize	circuits using SPLDs and FPGAs by applying decomposition theorems and logic optimization techniques.
combinational/sequential circuits using SPLDs. 3. Analyze the resource blocks of FPGAs and compare them with ASICs, microprocessors, and GPUs.	4. Develop FSM-based systems (e.g.,
4. Implement FPGA-based designs using industry-standard tools (Xilinx	counters, controllers) with optimized state encoding and validate them through timing diagrams.
Vivado) covering simulation, synthesis, and optimization. 5. Design and optimize Finite State Machines (FSMs) using	 Compare FPGA architectures with other computing platforms (ASICs, GPUs) and justify their use in real-world applications (e.g., DSP, embedded
Mealy/Moore models and evaluate trade-offs	systems).

CO 1 O 14	apping				
СО	PO1	PO2	PO3	PO4	PO5
CO1	1	1	3		
CO2	2	1	3		
CO3	2	1	3	2	
CO4	2	1	3	3	
CO5	3	1	3	2	

UNIT - I:

Programmable Logic Devices (PLDs): Introduction to Simple Programmable Logic Devices (SPLDs), Programmable Read Only Memory (PROM), Programmable Logic Array (PLA), Programmable Array Logic (PAL), Comparison of PLDs, Programming methods for PLDs, Applications of PLDs.

UNIT - II:

Realization of Logic Functions using SPLDs: Concept of logic synthesis, Shanon's expansion / decomposition theorem, Principles of operation of PROMs, Design procedure with PROMs, Logic function implementation with PROMs, Principles of operation of PLA, Design procedure with PLA, Logic function implementation with PLA, Principles of operation of PAL, Design procedure with PAL, Logic function realization with PAL.

UNIT - III:

Field Programmable Gate Arrays (FPGAs): Architecture and Basic building blocks and resource blocks of FPGAs, Configurable Logic Blocks (CLBs), IO Block, Programming methods, Anti fuse, SRAM and EPROM based FPGAs, Comparison with ASICs, microprocessors, and GPUs., Implementation examples of logic function using LUTs and CLBs

UNIT - IV: FPGA Design Flow

Design Entry & Simulation: Tools: Xilinx Vivado, Synthesis & Implementation: Constraints (timing, pin assignments), Understanding synthesis reports, Place & Route Optimization: Critical path analysis, resource utilization

UNIT - V: Finite State Machines: Realization of sequential circuits, State diagram, state table, state assignment, choice of flipflops, Timing diagram, One hot encoding, Mealy and Moore state machines, State minimization, System Design examples

Learning Resources:

- P.K. Chan & S. Mourad, Digital Design Using Field Programmable Gate Array, Pearson Education 2009.
- 2. Wayne Wolf, FPGA based System Design, Pearson Education 2009.
- 3. Steve Kilts, Advanced FPGA Design: Architecture, Implementation and optimization, A Jhon Wiley & Sons, Inc., publication.
- 4. Pong P Chu, "FPGA Proto Typing by Verilog Examples" WILEY Publications.
- 5. Data sheets and Manuals from Xilinx, Altera, AMD, Actel.

The break-up of CIE: Internal	Tests + Assignments + Quizzes
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1. No. of Internal Tests : 2 Max. Marks for each Internal Tests : 30

2. No. of Assignments : 3 Max. Marks for each Assignment : 5

3. No. of Quizzes : 3 Max. Marks for each Quiz Test : 5

VASAVI COLLEGE OF ENGINEERING (AUTONOMOUS) Accredited by NAAC with 'A++' Grade IBRAHIMBAGH, HYDERABAD – 500 031

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Scripting Languages

Professional Elective - II SYLLABUS FOR M.E. ECE (ES&VLSID) - I SEMESTER

L:T:P (Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P25PE150EC
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

COURSE OBJECTIVES	COURSE OUTCOMES
1. To understand control structures of	On completion of the course, students
perl.	will be able to
2. To classify character classes.	Design control structures of perl.
3. To apply subroutines and data	2. Apply subroutines and data
structures.	structures.
4. To acquire the knowledge extending	
perl.	4. Classify character classes.
5. To understand broad features of	5. Model features of SKILL, CGI.
SKILL, CGI.	

CO-PO Mapping

	·~PP3				
CO	PO1	PO2	PO3	PO4	PO5
CO1			2		1
CO2			2		1
CO3			2		1
CO4			2		1
CO5			2		

UNIT – I

Overview of scripting languages-PERL, file handles, operators, control structures, regular expressions, built in data types, operators, statements and declarations- simple, compound, loop statements, global and scoped declarations.

UNIT - II

Pattern matching - regular expression, pattern matching operators, character classes, positions, capturing and clustering.

UNIT - III

Subroutines- syntax, semantics, proto types, format variables, references, data structures- arrays of arrays, hashes of arrays, hashes of functions. Inter process communication,- signals, files, pipes, sockets,.

UNIT - IV

Threads- process model, thread model, Perl debugger- using debugger commands, customization, internals and externals, internal data types, extending Perl, embedding Perl, exercises for programming using Perl.

UNIT - V

Other languages: Broad features of other scripting languages SKILL, CGI, java script, VB script.

Learning Resources:

- Larry Wall, Tom Christiansen, John Orwant, "programming perl", oreilly publications, 3rd edition.
- 2. Randal L, Schwartz Tom Phoenix, "Learning PERL", Oreilly publications.

The break-up of CIE: Internal Tests + Assignments + Quizzes

- 1. No. of Internal Tests : 2 Max. Marks for each Internal Tests : 30
- 2. No. of Assignments : 3 Max. Marks for each Assignment : 5
- 3. No. of Quizzes : 3 Max. Marks for each Quiz Test : 5

DEPARTMENT OF MECHANICAL ENGINEERING

Research Methodology and IPR

SYLLABUS FOR M.E. - I SEMESTER

L	L:T:P (Hrs./week) : 2:0:0	SEE Marks: 60	Course Code: P25PC140ME
(Credits: 2	CIE Marks: 40	Duration of SEE: 3 Hours

COURSE OBJECTIVES	COURSE OUTCOMES
The objectives of this course are to:	On completion of the course, students
1.Learn the research methodology and	will be able to
formulation.	1. Explain objectives of research and
2. Know the sources of literature, method	research process.
for collection of research data and	2. Search the relevant literature and
report writing.	summarize information for
3. Understand IPR laws and Acts.	formulating the research problem.
	3. Collect and organize the data for the
	preparation of research report.
	4. Explain different types of intellectual
	property rights and related laws.
	5. Understand the patent
	administration system.

CO-PO Mapping						
CO	PO1	PO2	PO3	PO4	PO5	
CO1	2	2	1		1	
CO2	2	2	1		1	
CO3	2	2	1		1	
CO4	2	2	1		1	
CO5	2	2	1		1	

UNIT - I

Research Methodology: Meaning of research, Objectives and motivation of research, types of research, research approaches, significance of research, research methods versus methodology, criteria of good research, Research problem formulation.

UNIT - II

Literature survey: Importance of literature survey, sources of information, Literature review: Need of Literature review, Plagiarism, research ethics, errors in research, Assessment of quality of journals.

UNIT - III

Data collection & report preparation: Collection of primary data, secondary data, data organization, methods of data grouping, diagrammatic

representation of data, graphic representation of data. Effective technical writing and how to write report, format of a research proposal, contents of a standard technical journal/conference paper, contents of dissertation.

UNIT - IV

Introduction to Intellectual property law: Basics and types of intellectual property, international organizations, agencies and treaties.

Law of Trademarks: Purpose and functions of trademarks, types of Marks, acquisition of trade mark rights, protectable matter and trade mark registration process, Trade Mark Act.

UNIT-V

Law of copyrights: Introduction, common law rights. Rights of reproduction, rights to display work publicly, other limitations of exclusive rights, copyright ownership issues, copy right registration and Berne convention.

Law of Patents: Administration of Indian patent system, Introduction, rights under patent law. Design patents, Plant patents. Patenting process. Patent ownership and transfer, new developments in IPR and international patent laws, Geographical Indications.

Learning References:

- 1. Stuart Melville and Wayne Goddard, "Research methodology: an introduction for science & engineering students'.
- 2. C. R. Kothari-Research Methodology Methods and Techniques, Second revised edition, New Age International (P) limited Publishers, New Delhi.2013.
- 3. Ranjitkumar, Research methodology, A step-by-step Guide for Beginners, second Edition, Sage Publications India Pvt. Ltd, New Delhi.2017.
- Panneer Selvam, Research Methodology, Second Edition, PHI Learning Pvt. Ltd, New Delhi.
- Deborah E. Bouchoux -Intellectual Property, the law of trademarks, Copyrights, Patents and Trade Secrets. Fourth Edition, CENGAGE Learning India private Limited, New Delhi.2013.
- 6. P. Narayana, Intellectual property law, Third Edition, Eastern Law House, New Delhi.

The break-up of CIE: Internal	Tests + Assignments +	Quizzes
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1.	No. of Internal Tests	: 2	Max. Marks for each Internal Tests	:	30
2	No of Assignments	. 2	May Marks for each Assignment		Е

No. of Assignments : 3 Max. Marks for each Assignment : 5
 No. of Quizzes : 3 Max. Marks for each Quiz Test : 5

DEPARTMENT OF HUMANITIES AND SOCIAL SCIENCES

English for Research Paper Writing

Audit Course - I SYLLABUS FOR M.E. - I SEMESTER

L:T:P (Hrs./week) : 2:0:0	SEE Marks: 60	Course Code: P25AC110EH
Credits : -	CIE Marks: 40	Duration of SEE : 3 Hours

	COURSE OBJECTIVES	COURSE OUTCOMES		
	e course will enable the learners to: Understand, how to improve writing skills and level of readability. Learn about what to write in each	At the end of the course the learners will be able to: - 1. Write research papers 2. Write citations as per the MLA		
3	section. Understand the skills needed whenwriting a Title Ensure the good quality of paper atvery first-time submission	stylesheet and APA format 3. Write concisely and clearly following therules of simple grammar, diction and coherence.		

UNIT-I: Foundations of Academic Writing

Planning and Preparation, Word Order, Breaking up long sentences. Structuring Paragraphs and Sentences, Being concise and Removing Redundancy, Avoiding Ambiguity and Vagueness

UNIT-II: Presenting Research Effectively

Clarifying Who Did What, Highlighting your Findings, Hedging and Criticizing, Paraphrasing and Plagiarism, Sections of a Paper, Abstracts, Introduction

UNIT-III: Structuring the Research Paper

Review of the Literature, Methods, Results, Discussion, Conclusions, The Final Check.

UNIT-IV: Crafting Impactful Research Components (Part I)

Key skills are needed when writing a Title, key skills are needed when writing an Abstract, key skills are needed when writing an Introduction, skills needed when writing a Review of the Literature, useful phrases, how to ensure paper is as good as it could possibly be the first-time submission.

UNIT-V: Crafting Impactful Research Components (Part II)

Skills are needed when writing the Methods, skills needed when writing the Results, skills are needed when writing the Discussion, skills are needed when writing the Conclusions.

METHODOLOGY ASSESSMENTS

- Case Studies

- Online assignments

- Demonstration

- Individual and Group

- Presentations
- Expert lectures
- Writing and Audio-visual lessons

Learning Resources:

learn.talentsprint.com

- Goldbort R (2006) Writing for Science, Yale University Press (available on Google Books)
- Day R (2006) How to Write and Publish a Scientific Paper, Cambridge University Press
- 3. Highman N (1998), Handbook of Writing for the Mathematical Sciences, SIAM Highman's book.
- 4. Adrian Wallwork, English for Writing Research Papers, Springer New York Dordrecht Heidelberg London, 2011.

The	The break-up of CIE: Internal Tests + Assignments + Quizzes					
1.	No. of Internal Tests	:	2	Max. Marks for each Internal Tests	:	30
2.	No. of Assignments	:	3	Max. Marks for each Assignment	:	5
3.	No. of Quizzes	:	3	Max. Marks for each Quiz Test	:	5

VASAVI COLLEGE OF ENGINEERING (AUTONOMOUS) Accredited by NAAC with 'A++' Grade IBRAHIMBAGH, HYDERABAD – 500 031

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Advanced Embedded Systems Laboratory

SYLLABUS FOR M.E. ECE (ES&VLSID) - I SEMESTER

L:T:P (Hrs./week): 0:0:4	SEE Marks : -	Course Code: P25PC111EC
Credits: 2	CIE Marks: 50	Duration of SEE : -

COURSE OBJECTIVES	COURSE OUTCOMES
1. Design Embedded Systems by using ARM Cortex M4x based MCU as the CPU.	On completion of the course, students will be able to 1. Program ARM based microcontroller
Implement real world interfacing with ARM and design prototypes.	using its assembly constructs. 2. Implement C constructs to design ARM based embedded system. 3. Interface real world input and output devices to ARM 4. Design and execute a mini project for the given specifications. 5. Propose different debugging methods
CO DO Marriag	for implementing embedded systems.

CO-PO Mapping PO1 PO₂ PO3 PO4 PO5 CO1 1 2 3 2 CO2 1 2 3 2 CO3 3 2 CO4 1 2 CO5

List of Experiments using Embedded C/Embedded C++:

Module – 1 (ARM Cortex M4 Assembly Language Programming)

- ARM Data formats and Directives.
- 2. Addressing Modes.
- 3. Arithmetic & Logical instructions
- 4. Looping and Branching Instructions
- 5. Conditional Subroutines
- 6. ARM Conditional Execution in Assembly

Module-2 (STM32F4xxx MCU based SBC)

- 7. GPIO Programming
- 8. Interfacing 7-segment display.
- 9. Interfacing a 4x4 Matrix keyboard for input and 2x16 LCD for output.
- 10. Developing user interface for ARM.
- 11. Timer Programming
- 12. Full duplex UART Driver design in Embedded C.

Suggested tools for used:

- 1. Hardware Target CPU; STM32F4xx (ARM CortexM4F from ST.
- 2. Embedded Compiler Keil µVision5 IDE: ARM compiler
- 3. Embedded Debugger Keil µVision5 Debugger
- 4. Hardware Simulator Proteus 8.x

The break-up of CIE:

1. No. of Internal Test : 1

2. Max. Marks for each internal tests : 20

3. Marks for assessment for day to day evaluation : 30

Duration of Internal Test: 3 Hours

VASAVI COLLEGE OF ENGINEERING (AUTONOMOUS) Accredited by NAAC with 'A++' Grade IBRAHIMBAGH, HYDERABAD – 500 031

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Analog and Digital VLSI Design Laboratory

SYLLABUS FOR M.E. ECE (ES&VLSID) - I SEMESTER

L:T:P (Hrs./week): 0:0:4	SEE Marks : -	Course Code: P25PC121EC
Credits: 2	CIE Marks: 50	Duration of SEE : -

COURSE OBJECTIVES	COURSE OUTCOMES
To demonstrate computer aided design tools for the modeling, design, analysis and verification of digital and analog integrated circuits.	On completion of the course, students will be able to 1. Develop HDL code for combinational and sequential logic circuits and Synthesize them. 2. Verify the designs using system Verilog.
	3. Design and simulate analog circuits.

CO-PO Mapping

	CO I O I Iupping						
CO	PO1	PO2	PO3	PO4	PO5		
CO1	3	-	3	3	-		
CO2	3	-	3	3	-		
CO3	3	-	3	3	-		

Part A

- 1. Design and simulate Adder /Counter using Verilog HDL.
- 2. ASIC Synthesis of Adder/ Counter and find its performance parameters.
- 3. Design and Simulate a traffic signal controller using finite state machine.
- 4. Verify functionality of adder with test bench using System Verilog.
- 5. Verify functionality of Counter with test bench using System Verilog.
- 6. Insert clock gating for power optimization in Counter.

 Note: Above experiments are to be carried out using Cadence tools (incisive simulator and genus)

PART B

- 7. Design and Simulation of Symmetrical CMOS inverter and evaluate its performance.
- 8. Design and simulate a 6-T SRAM cell and find its parameters.
- 9. Design and simulation of current mirror and plot its behavior.

- 10. Simulate a single stage MOS amplifier with two different loads and compare their performance.
- 11. Design and Simulate a differential amplifier with active load.
- 12. Design and simulate a general purpose CMOS OPAMP.

Note: Above experiments are to be carried out using Cadence tools (virtuoso Schematic composer and spectre circuit simulator)

Note: Minimum of ten experiments are to be conducted.

The break-up of CIE:

1. No. of Internal Test : 1

2. Max. Marks for each internal tests : 20

3. Marks for assessment for day to day evaluation : 30

Duration of Internal Test: 3 Hours

Syllabus for M.E. ECE (ES & VLSI Design) II - SEMESTER

Duration of SEF : 3 Hours

Credits · 3

VASAVI COLLEGE OF ENGINEERING (Autonomous) Accredited by NAAC with 'A++' Grade IBRAHIMBAGH, HYDFRABAD - 500 031

DEPARTMENT OF FLECTRONICS AND COMMUNICATION ENGINEERING

Embedded Real Time Operating Systems

Professional Core - III SYLLABUS FOR M.E. ECE (ES&VLSID) - II SEMESTER

L:T:P (Hrs./week): 3:0:0 Course Code: P25PC210EC SFF Marks: 60 CIF Marks · 40

COURSE OBJECTIVES	COURSE OUTCOMES
Understand the fundamentals of RTOS	On completion of the course, students will be able to 1. Differentiate OS, RTOS and classify Real-Time
2. Study the task	kernels.
management and scheduling algorithms	2. Demonstrate the use of different scheduling algorithms to estimate the deadline and propose
3. Explore the Linux kernel structure and its process	different inter-task-communication models opted in RTOS.
management 4. Understand the various	3. Describe Linux kernel architecture and process management.
device drivers and debugging techniques in	 Differentiate Linux user space processes and kernel space threads and implement device drivers using
Linux 5. Apply RTOS concepts in	Shell APIs. 5. Suggest fault tolerance methods for real time
industry-relevant case	

studies

со-го маррину						
СО	PO1	PO2	PO3	PO4	PO5	
CO1	3	3	2			
CO2	2	2	1			
CO3	2	2	1			
CO4	3	2	2	1	1	
CO5	1	1	2	1	1	

systems

UNIT-I

Concept of Embedded Operating Systems, Differences between Traditional OS and RTOS; Architecture of RTOS, Kernels - classifications, importance of scheduler in OS: objectives and functions; Hard versus Soft Real-time systems – examples, Jobs & Processes, timing constraints. Pre-emptive Vs Non-preemptive kernels.

UNIT-II

Task Priorities, Scheduling, inter task Communication & Synchronization -Definition of Context Switching, Foreground ISRs and Background Tasks. Critical Section: Re- entrant Functions, Inter Process Communication (IPC) - IPC through Semaphores, Mutex, Mailboxes, Message Queues or Pipes and Event Flags.

Scheduling Algorithms - RMS, Preemptive EDF scheduling - principle, comparisons.

UNTT-TTT

Linux Kernel 2.x architecture - File system, Concepts of Process - creation, Process Control Block (PCB); process Vs thread; Concurrent Execution, Process Management in Linux-forks Vs Vfork; process state transitions, zombie state, Memory Management Algorithms.

UNIT-IV

Device Drivers & Communication with Hardware - Definition; advantages of Modules; kernel space Vs user space; Concurrency and Race Conditions; classification of device drivers – character drivers, block drivers and net drivers, Interrupt handling in RTOS, Debugging Techniques.

UNTT-V

Fault-Tolerance Techniques & RTOS Application Domains: What causes failures, Fault types, Fault detection, Hardware and software Redundancy. Case studies of RTOS-RTOS for Image Processing - Embedded RTOS for AI and ML applications – RTOS for fault Tolerant Applications – RTOS for Control Systems.

Learning Resources:

- Jean J. Labrosse, "Embedded Systems Building Blocks: Complete and Ready-to- Use Modules in C", CMP Publishers Jan 1999.
- Robert Love, "Linux Kernel Development" (3rd Edition), Novell Press 2010.
- Jane W.S. Liu, Real Time Systems, Pearson Education, Asia, 2001.
- Jonathan Corbet, Alessandro Rubini, Greg Kroah-Hartman, "Linux Device Drivers", 3rd Edition, O'Reilly Media Publishers Real Time Systems, C.M. Krishna and G. Shin, McGraw-Hill Companies Inc.,
- McGraw Hill International Editions, 1997.

The break-up of CIE: Internal Tests + Assignments + Quizzes 2 : 30 1. No. of Internal Tests Max. Marks for each Internal Tests

5 Max. Marks for each Assignment 2. No. of Assignments

No. of Ouizzes Max. Marks for each Ouiz Test 5 3.

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

VLSI Physical Design

Professional Core - IV

SYLLABUS FOR M.E. ECE (ES&VLSID) - II SEMESTER

L:T:P (Hrs./week) : 3:0:0	SEE Marks: 60	Course Code: P25PC220EC	
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours	

COURSE OBJECTI	VES	COURSE OUTCOMES
1. To understand the str	ructures O	On completion of the course, students will be able to
of different compone	ents of 1	. Design the structures of different components of VLSI
VLSI design.		design.
2. To draw stick and	layout 2	. Apply the basic concepts of physical design to layouts and
diagrams of circuits.		stick diagrams.
3. To acquire the knowledge	edge of 3	. Apply Design rules for layouts of circuits.
cell based designs.		. Design hierarchical circuit Layouts using cell concepts.
	5	. Analyze the basic algorithms which are involved in the
		process of physical design automation.

CO-PO Mapping

	~PP9				
CO	PO1	PO2	PO3	PO4	PO5
CO1				2	
CO2				2	
CO3			1	3	
CO4				3	
CO5	1			2	

UNIT - I

VLSI Design cycles and new trends in Design cycles, physical design cycles and new trends in physical design cycles, Components of VLSI, Various layers of VLSI, Typical structures of BJTS, MOSFETS, Resistors, capacitors, inductors ,Brief review of technology, cost and performance analysis.(Reference 1)

UNIT - II

Basic concepts of Physical Design - layout of basic structures – wells, FET, BJT, resistors, capacitors, contacts, vias and wires (Interconnects), physical design of logic gates – NOT, NAND and NOR. Mask overlays for different structures. Parasitics – latch up and its prevention. Device matching and common centroid techniques for analog circuits(Reference 1 and 3)

UNIT - III

Design rules – fabrication errors, alignment sequence and alignment inaccuracies, process variations and process deltas, drawn and actual dimensions and their effect

on design rules— scalable design rules. Scalable CMOS (SCMOS) design rules, layout design, and stick diagrams, Hierarchical stick diagrams. (Reference 4)

UNIT - IV

Cell concepts – cell based layout design – Wein-berger image array — design hierarchies. System level physical design- large scale physical design , interconnect delay modeling,cross talk, floor planning, routing and clock distribution.(Reference1 and 3)

UNIT - V

Factors, Complexity Issues and NP-hard Problems, Basic Algorithms (Graph and Computational Geometry): Basic terminology, graph search algorithms, spanning tree algorithms, shortest path algorithms, matching algorithms, min-cut and max-cut algorithms. Steiner tree algorithms, (Referene 1 and 2)

Learning Resources:

- Algorithms for VLSI Physical Design automation, Naveed Sherwani.3rd edition Kluwer academic publishers
- 2. Algorithms for VLSI Design automation, Sabith H.Gerez ,John Wiley & sons, Inc.
- 3. John P. Uyemura, Introduction to VLSI Circuits and Systems, John Wiley & sons, Inc.
- 4. Modern VLSI Design (System on Chip), Woyne Wolf, Pearson Education, 2002.
- R. Jacob Baker; Harry W.Li., David E. Boyce, CMOS Circuit Design, Layout and Simulation, IEEE Press, Prentice Hall of India.

The break-up of CIE: Internal Tests + Assignments + Quizzes

1. No. of Internal Tests : 2 Max. Marks for each Internal Tests : 30

2. No. of Assignments : 3 Max. Marks for each Assignment : 5

3. No. of Ouizzes : 3 Max. Marks for each Ouiz Test : 5

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Hardware-Software Co-design

Professional Elective - III SYLLABUS FOR M.E. ECE (ES&VLSID) - II SEMESTER

L:T:P (Hrs./week) : 3:0:0	SEE Marks: 60	Course Code: P25PE210EC
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

COURSE OBJECTIVES		COURSE OUTCOMES
To understand architectures, c methodology and design	:	On completion of the course, students will be able to 1. Identify the need for co-design 2. Model data flow and implement the same through software and hardware 3. Construct data flow and control flow graphs 4. Design data flow model for a FSM 5. Design an SoC for given application

UNIT -I

Co- Design Issues: Co- Design Models, Architectures, Languages, A Generic Co-design Methodology. Co- Synthesis Algorithms: Hardware software synthesis algorithms: hardware – software partitioning distributed system co-synthesis.

UNIT -II

Prototyping and Emulation: Prototyping and emulation techniques, prototyping and emulation environments, future developments in emulation and prototyping architecture specialization techniques, system communication infrastructure. Target Architectures: Architecture Specialization techniques, System Communication infrastructure, Target Architecture and Application System classes, Architecture for control dominated systems (8051-Architectures for High performance control), Architecture for Data dominated systems (ADSP21060, TMS320C60), Mixed Systems.

UNIT -III

Compilation Techniques and Tools for Embedded Processor Architectures: Modern embedded architectures, embedded software development needs, compilation technologies, practical consideration in a compiler development environment.

UNTT -TV

Design Specification and Verification: Design, co-design, the co-design computational model, concurrency coordinating concurrent computations, interfacing components, design verification, implementation verification, verification tools, interface verification

UNTT -V

Languages for System – Level Specification and Design-I: System – level specification, design representation for system level synthesis, system level specification languages, Languages for System – Level Specification and Design-II: Heterogeneous specifications and multi language co-simulation, the cosyma system and lycos system.

Learning Resources:

- 1. Hardware / Software Co- Design Principles and Practice Jorgen Staunstrup, Wayne Wolf –2009, Springer.
- Hardware / Software Co- Design Giovanni De Micheli, Mariagiovanna Sami, 2002, Kluwer Academic Publishers.
- 3. A Practical Introduction to Hardware/Software Co-design -Patrick R. Schaumont 2010 Springer

The	e break-up of CIE: Inter	nal	Test	ts + Assignments + Quizzes		
1.	No. of Internal Tests	:	2	Max. Marks for each Internal Tests	:	30
2.	No. of Assignments	:	3	Max. Marks for each Assignment	:	5
3.	No. of Quizzes	:	3	Max. Marks for each Quiz Test		5

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Design Verification using System Verilog

Professional Elective - III
SYLLABUS FOR M.E. ECE (ES&VLSID) - II SEMESTER

L:T:P (Hrs./week) : 3:0:0	SEE Marks: 60	Course Code: P25PE220EC
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

	COURSE OBJECTIVES		COURSE OUTCOMES
1	Students will build a layered test bench	On	completion of the course, students will be able to
	and simulate a simple ligic block	1	Identify the need for a test bench and specify the
2	They will learn the important features		formal verification techniques (PO2)
	of System Verilig	2	Implement simulation based verification of a
3	They will develop a test bench using		given system (PO2)
	object oriented concepts for veryfying a	3	Implement a formal test bench using object
	digital system		oriented concepts for veryfying a digital system.
4	They will understand the limitations of		(PO3)
	Randomization of functions and	4	Model hardware interfaces with concurrency
	implement random device configuration		constructs. (PO3)
5	They will connect the test bench and	5	CO5 Investigate the interface between the test
	design of a given system		bench and the design of a given system using
			IEEE1800 Verilog assertions.(PO4)

CO-PO	Man	nına
	···up	PIIIS

	~				
CO	PO1	PO2	PO3	PO4	PO5
CO1			2	2	1
CO2			2	2	1
CO3			2	2	1
CO4			2	2	1
CO5			2	2	1

UNIT - I

Verification Methodologies: The Verification Process, The Verification Plan, The Verification Methodology Manual, Basic Testbench Functionality, Directed Testing, Methodology Basics, Constrained-Random Stimulus, What Should You Randomize, Functional Coverage, Testbench Components, Layered Testbench, Building a Layered Testbench, Simulation Environment Phases, Maximum Code Reuse, Testbench Performance, Conclusion.

UNIT - II

Fundamentals of System Verilog: DATA TYPES, Built-in Data Types, Fixed-Size Arrays, Dynamic Arrays, Queues, Associative Arrays, Linked Lists, Array Methods, Choosing a Storage Type, Creating New Types with typedef, Creating User-Defined Structures, Enumerated Types, Constants, Strings, Expression Width, Net Types, Conclusion, PROCEDURAL STATEMENTS AND ROUTINES,

Introduction Procedural Statements, Tasks, Functions, and Void Functions, Task and Function Overview, Routine Arguments, Returning from a Routine, Local Data Storage, Time Values.

UNTT - TIT

Object Oriented Concepts for verification: Think of Nouns, not Verbs, Your First Class, Where to Define a Class, OOP Terminology, Creating New Objects, Object Deallocation, Using Objects, Static Variables vs. Global Variables, Class Routines, Defining Routines Outside of the Class, Scoping Rules, Using One Class Inside Another, Understanding Dynamic Objects, Copying Objects, Public vs. Private, Straying Off Course, Building a Testbench.

UNIT - IV

RANDOMIZATION Techniques for Verification : What to Randomize, Randomization in SystemVerilog, Constraint Details, Solution Probabilities, Controlling Multiple Constraint Blocks, Valid Constraints, In-line Constraints, The pre_randomize and post_randomize Functions, Constraints Tips and Techniques, Common Randomization Problems, Iterative and Array Constraints, Atomic Stimulus Generation vs. Scenario Generation, Random Control, Random Generators, Random Device Configuration.

UNIT-V

CONNECTING THE TESTBENCH AND DESIGN: Separating the Testbench and Design, The Interface Construct, Stimulus Timing, Interface Driving and Sampling, Connecting It All Together, Top-Level Scope, Program – Module Interactions, SystemVerilog Assertions, The Four-Port ATM Router.

Learning Resources:

1. CHRIS SPEAR Synopsys, Inc. "SYSTEMVERILOG FOR VERIFICATION A Guide to Learning the Testbench Language Features" Springer.

The break-up of CIE: Internal Tests + Assignments + Quizzes

1. No. of Internal Tests : 2 Max. Marks for each Internal Tests : 30
2. No. of Assignments : 3 Max. Marks for each Assignment : 5

3. No. of Ouizzes : 3 Max. Marks for each Ouiz Test : 5

DEPARTMENT OF FLECTRONICS AND COMMUNICATION ENGINEERING

Static Timing Analysis

Professional Elective - III
SYLLABUS FOR M.E. ECE (ES&VLSID) - II SEMESTER

L:T:P (Hrs./week) : 3:0:0	SEE Marks: 60	Course Code: P25PE230EC
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

COURSE OBJECTIVES	COURSE OUTCOMES
COURSE OBJECTIVES	COURSE OUTCOMES
Students will	On completion of the course, students will be able to
1 understand clock domains and critical paths in a given logic design	Identify critical paths and estimate propagation delays and skews in a given data-path (PO1 and)
2 Interpret extracted parasitics and	PO2)
reduce parasitics in critical paths	2. Compare the performance of Elmore delay model
3 Estimate the Interconnect delays and	and higher order interconnect delay models (PO3)
calculate multiple path slacks	3. Analyse Cross-talk Noise and its reduction in a given
4 Perform cross-talk and Noise analysis	data path (PO2)
in a given net	4. Perform timing analysis across multicycle paths and
5 Perform timing analysis and	interpret the results (PO2, PO5)
verification across multicycle paths and clock domains	5. Estimate the timing across multiple clock domains and refine the timing by path balancing (PO2, PO3 and PO5)

UNIT - I:

STA Concepts : CMOS Logic Design, Basic MOS Structure, CMOS Logic Gate, Standard Cells, Modeling of CMOS Cells, Switching Waveform, Propagation Delay, Slew of a Waveform, Skew between Signals, Timing Arcs and Unateness, Min and Max Timing Paths, Clock Domains, Operating Conditions.

UNIT - II:

Interconnect Parasitics: RLC for Interconnect, T-model, Pi-model, Wireload Models, Interconnect Trees, Specifying Wireload Models, Representation of Extracted Parasitics, Detailed Standard Parasitic Format, Reduced Standard Parasitic Format, Standard Parasitic Exchange Format, Representing Coupling Capacitances, Hierarchical Methodology, Block Replicated in Layout, Reducing Parasitics for Critical Nets, Reducing Interconnect Resistance, Increasing Wire Spacing, Parasitics for Correlated Nets.

UNIT - III:

Delay Calculations: Delay Calculation Basics, Delay Calculation with Interconnect, Prelayout Timing, Post-layout Timing, Cell Delay using Effective Capacitance, Interconnect Delay, Elmore Delay, Higher Order Interconnect Delay Estimation, Full Chip Delay Calculation, Slew Merging, Different Slew Thresholds, Different Voltage Domains, Path Delay Calculation, Combinational Path Delay, Path to a Flip-flop, Input to Flip-flop Path, Flip-flop to Flip-flop Path, Multiple Paths Slack Calculation.

UNIT - IV:

Crosstalk and Noise Analysis: Crosstalk Glitch Analysis, Basics Types of Glitches, Rise and Fall Glitches, Overshoot and Undershoot Glitches, Glitch Thresholds and Propagation, DC Thresholds, AC Thresholds, Noise Accumulation with Multiple Aggressors, Aggressor Timing Correlation, Aggressor Functional Correlation, Crosstalk Delay Analysis, Basics, Positive and Negative Crosstalk, Accumulation with Multiple Aggressors, Aggressor Victim Timing Correlation, Aggressor Victim Functional Correlation, Timing Verification Using Crosstalk Delay, Setup Analysis, Hold Analysis, Computational Complexity, Hierarchical Design and Analysis, Filtering of Coupling Capacitances, Noise Avoidance Techniques.

UNIT - V:

STA Environment & Timing Verification: What is the STA Environment, timing issues, Generated Clocks, Example of Master Clock at Clock Gating Cell Output, Constraining Output Paths, Timing Path Groups, Modeling of External Attributes, Modeling Drive Strengths, Modeling Capacitive Load, Design Rule Checks, Virtual Clocks, Refining the Timing Analysis, Multicycle Paths, Crossing Clock Domains, False Paths, Half-Cycle Paths, Removal Timing Check, Recovery Timing Check, Timing across Clock Domains, Examples, Half-cycle Path - Case 1, Half-cycle Path - Case 2, Fast to Slow Clock Domain, Slow to Fast Clock Domain, Multiple Clocks.

Learning Resources:

1. J. Bhasker, Rakesh Chadha "Static Timing Analysis for Nanometer Designs A Practical Approach" springer, 2009.

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3. No. of Quizzes : 3 Max. Marks for each Quiz Test : 5

DEAPRIMENT OF HUMANITIES AND SOCIAL SCIENCES.

Pedagogy Studies

Audit Course - II SYLLABUS FOR M.E. - II SEMESTER

L:T:P(Hrs./week): 2:0:0	SEE Marks: 60	Course Code: P25AC210EH
Credits : -	CIE Marks: 40	Duration of SEE: 3 Hours

	COURCE OBJECTIVES	COURCE OUTCOMES
	COURSE OBJECTIVES	COURSE OUTCOMES
Obj	ectives of this course are to get students:	Upon the completion of this course the
1.	Understand and identify different	students will be expected to:
	behavioural styles and adapt training as	1. Do a Learning Style inventory and
	necessary.	understand theirs, and their students'
2.	Identify the characteristics of an	learning style
	exceptional facilitator	2. Demonstrate successful understanding of
3.	Understand and identify different	key concepts during a practice
	behavioural styles and adapt training as	presentation.
	necessary.	3. Do a need analysis and why it is a
4.	Understand how to make lecture-based	necessary step in any training program.
''	programs active.	4. Develop strategies for different types of
5.	Make effective trainer aids such as	learners, handling hecklers, bullies, and
	power points and learn to identify all the	other disruptive participants
	dependencies	5. Present information in a clear, concise,
	dependencies	engaging manner.

From Fabulous to Fantastic -The Art and Science of Teaching the Digital Generation

Keeping information fresh and reinforcing new learning is a constant challenge for an instructor imparting knowledge to an adult. How do you choose activities that are fun but meaningful? How do you assess the level of knowledge already in the room? Is there a formula for creating a successful learning session?

This course is designed to nurture the process of learning, to facilitate sharing of field level experience and giving constructive feedback on training style and delivery. This Audit Course will teach participants how to determine the needs of an audience, improve classroom charisma, handle difficult participants, use activities effectively, and more.

Course Outline

UNIT-1 - Astounding Adults: How they learn

Teaching adults calls for trustworthiness and neutrality while keeping the discussion focused. The first two sessions are about how adults learn how to help in retention and recall.

- How do adults learn
- Pedagogy and Andrago
- Malcolm Knowles theory of Andragogy
- Neuro Linguistic programming
- Kolb's learning styles
- Helping adults learn

UNIT-2 - Classic Course/Class Design

This section's focus is on creating a classic course design that is tailor made for the trainee's learning style. This section also focuses on assessing the trainees' needs in class and customizes activities/direct discussions to address these needs. This section is delivered in two sessions.

- Six thinking hats and the classic course design
- Creating a beautiful body
- Opening
- Main body
- Grand finale

Unit 3 -Beating Murphy's Law

This section is designed to help trainers make effective trainer aids such as power points and learn to identify all the dependencies in advance and have sufficient back up plans, in case there are technical issues. This section is spread over four sessions.

- Power Point
- The Rule of Three
- Anecdotes and Metaphors
- Beat Murphy's Law
- Awesome audiovisuals

Unit 4 - Dazzling Deliveries

Keeping trainees focused so they can get their desired results takes skill. Group dynamics and motivations can vary on many levels. Participants will learn how those factors affect facilitation. They will use tips shared in this session to practice re-engaging the audience through dialogue, feedback, and testing for consensus and understanding.

Training vs. facilitating vs. presenting

- Icebreakers
- Training Rainbow
- Teaching Style Tips
- Presenting and Demonstrating
- Teaching/Socratic Direction
- Facilitating discussion/brainstorming/increasing participation

Process Monitoring

Unit 5 - Fruitful Feedback

This Unit finishes with an important but sometimes forgotten skill of how to give and receive feedback. During an activity called What Would You Say? Participants evaluate their presentations and also do a peer evaluation and create an action plan on the following areas.

- Relevance of Content
- Level of Content
- Rating of the Presenters
- Knowledge Transfer
- Most Useful Aspect of the Course
- Least Useful Aspect of the Course
- Action plan to go from Fabulous to Fantastic

METHODOLOGY	ASSESSMENTS
- Case Studies	- Online assignments
- Demonstration	- Individual and Group
- Presentations	- Expert lectures
	- Writing and Audio-visual lessons

Suggested Books

The	e break-up of CIE:Inte	rnal Tests + Assignments + Quizzes	
1.	No. of Internal Tests	: 2 Max. Marks for each Internal Tests	: 30
2.	No. of Assignments	: 3 Max. Marks for each Assignment	: 5
3.	No. of Quizzes	: 3 Max. Marks for each Quiz Test	: 5

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Embedded System Applications Laboratory

SYLLABUS FOR M.E. ECE (ES&VLSID) - II SEMESTER

L:T:P(Hrs./week): 0:0:3	SEE Marks : -	Course Code: P25PC211EC
Credits: 2	CIE Marks: 50	Duration of SEE : -

	Course Objectives	Course Outcomes
1.	To Develop the Embedded	On completion of the course, students will
	applications using sensors	be able to
2.	To learn the interfacing with motors	Design Embedded Systems with C51
	and memory devices	target interfacing sensor and
3.	To implement the process	transducer for RT applications.
	management functions in Linux	2. Design and implement off-chip
4.	To implement the task scheduling	memories for embedded systems.
	algorithms in RTOS	3. Demonstrate host to ARM target
5.	To implement the IPC for RTOS	communication in embOS RTOS
		environment.
		4. Configure emPower board with
		embOS and validate different
		scheduling algorithms.
		5. Demonstrate different IPC schemes
		for multi-tasking in embOS and Linux
		OS.

CO-PO Mapping

CO	PO1	PO2	PO3	PO4	PO5
CO1	2	2	2	3	1
CO2	3	1	2	3	1
CO3	3	3	3	3	2
CO4	3	3	3	3	2
CO5	3	3	3	3	2

List of Experiments in RTOS using Embedded - C/C++:

- 1. Interfacing a sensor with ADC0804.
- 2. Multi-sensor interfacing with ADC0808.
- 3. Transducer interfacing with DAC0808 for generating a triangular, sawtooth sinusoidal waveforms.

- 4. Interfacing & controlling the DC Motor
- 5. Interfacing & controlling the stepper motor
- 6. Off-chip EEPROM 2KB/4KB interfacing for storing & retrieving lookup tables.
- 7. Emboss Real time task creation, Demonstration of Multitasking
- 8. SRAM interface design (1KB/4KB)
- 9. Interfacing with Timers & DS1307 RTC.
- 10. Implementation of fork, wait functions in Linux
- 11. Round Robin Scheduling of 2 Tasks in RTOS
- 12. Preemptive Scheduling of 2 Tasks in RTOS
- 13. IPC between 2 Tasks with Binary Semaphore
- 14. Mailbox usage for IPC between 2 tasks in RTOS

New / Additional experiments planned:

- Design a Round Robin with the interrupt driven scheduling in ARM by creating three tasks such that 2 tasks perform IPC with the same priority.
- 2. Porting of RTOS on Embedded target boards
- 3. Implementation RTOS scheduling of 3 tasks that has to wait for message Queue in Cortex M4F embOS for UI design.

Suggested tools for use:

- 1. Hardware Target CPU Cortex M4F power Segger Board, AT89S52
- 2. Embedded Software Development Embedded Studio V3.12a
- 3. Embedded Debugger Cortex M4F ARM Jlink
- 4. RTOS emboss

The break-up of CIE:

1. No. of Internal Test : 1

2. Max. Marks for each internal tests : 20

3. Marks for assessment for day to day evaluation : 30

Duration of Internal Test: 3 Hours

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

VLSI Physical Design Laboratory

SYLLABUS FOR M.E. ECE (ES&VLSID) - II SEMESTER

L:T:P(Hrs./week): 0:0:3	SEE Marks : -	Course Code: P25PC221EC
Credits: 2	CIE Marks: 50	Duration of SEE : -

COURSE OBJECTIVES	COURSE OUTCOMES
To Design and simulate basic building	On completion of the course, students
blocks of mixed signal IC's and perform	will be able to
full custom design of cells.	1. Perform floor planning, placement
	and routing of Adder/Counter.
	2. Perform layout and parasitic
	extraction of Adder/Counter.
	3. perform full custom design of
	basic gates and differential
	amplifier.

CO-PO Mapping

СО	PO1	PO2	PO3	PO4	PO5
CO1	3	-	3	3	-
CO2	3	-	3	3	-
CO3	3	-	3	3	-

Part A

- 1. Layout of basic gates. (inverter / Nand / NOR, Full custom design).
- 2. DRC and LVS of basic gates. (inverter / Nand /NOR, Full custom design).
- Parasitic extraction and Post layout simulation of basic gates. (inverter / Nand / NOR, Full custom design).
- 4. Floor planning, placement and routing of Adder.
- 5. Layout and parasitic extraction of Adder.
- 6. Static timing analysis and power analysis of Adder.
- 7. Floor planning, placement and routing of Counter.
- 8. Layout and parasitic extraction of Counter.

- 9. Static timing analysis and power analysis of Counter.
- 10. Layout of Differential Amplifier.
- 11. Parasitic extraction and post Layout simulation of Differential Amplifier.
- 12. Layout, Parasitic extraction and post layout simulation of 1 bit comparator.

Note: Above experiments are to be carried out using Cadence tools (virtuoso Layout editor, assura, spectre circuit simulator and innovus)

Note: Minimum of ten experiments are to be conducted.

The break-up of CIE:

1. No. of Internal Test : 1

2. Max. Marks for each internal tests : 20

3. Marks for assessment for day to day evaluation : 30

Duration of Internal Test: 3 Hours

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Mini Project with Seminar

SYLLABUS FOR M.E. ECE (ES&VLSID) - II SEMESTER

L:T:P (Hrs./week): 0:0:2	SEE Marks : -	Course Code: P25PW219EC
Credits: 2	CIE Marks: 50	Duration of SEE : -

COURSE OBJECTIVES	COURSE OUTCOMES
Prepare the student for a systematic and independent study of the state of the art topics in a broad area of his / her specialization.	 On completion of the course, students will be able to Selection of a suitable mini project topic / problem for investigation and presentation. Carryout literature survey and prepare the presentation. Formulating the problem, identify tools and techniques for solving the problems. Clear communication and presentation of the seminar topic. Apply ethical principles in preparation of seminar report.

CO-PO Mapping

CO-PO I	rapping				
CO	PO1	PO2	PO3	PO4	PO5
CO1	1	2	1	1	1
CO2	1	2	1	1	1
CO3	1	2	1	1	1
CO4	1	2	1	1	1
CO5	1	2	1	1	1

Oral presentation and technical report writing are two important aspect of engineering education. The objective of the Mini Project and seminar is to prepare the student for a systematic and independent study of the state of the art topics in the advanced fields of Embedded Systems, VLSI Design and related topics.

Mini Project topics may be chosen by the students with advice from the faculty members. Students are to be exposed to the following aspects for a seminar presentation.

- Literature survey
- Organization of the material
- Presentation of OHP slides / LCD presentation
- Technical writing

Each student required to:

- 1. Submit a one page synopsis before the seminar talk for display on the notice board.
- 2. Give a 20 minutes time for presentation following by a 10 minutes discussion.
- 3. Submit a detailed technical report on the seminar topic with list of references and slides used.

Seminars are to be scheduled from the 3rd week to the last week of the semester and any change in schedule shall not be entertained.

For award of sessional marks, students are to be judged by at least two faculty members on the basis of an oral and technical report preparation as well as their involvement in the discussions.

Syllabus for M.E. ECE (ES & VLSI Design) III - SEMESTER

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

High Level Synthesis

Professional Elective - IV
SYLLABUS FOR M.E. ECE (ES&VLSID) - III SEMESTER

L:T:P(Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P25PE310EC
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

Course Objectives	Course Outcomes
To expose the students, the basics of	On completion of the course, students
FPGA designs and synthesis.	will be able to
	1. Develop simple arithmetic modules and implement in FPGA .(PO1, PO5)
	2. Understand various libraries used in HLS based design (PO2)
	3. Apply various coding styles for FPGA
	synthesis and compare their performance (PO1, PO2)
	4. Compare the precision data types in
	System C and Vivado HLS (PO2, PO3)
	5. Synthesize a subsystem design using
	Vivado HLS and port it in FPGA (PO3,
	PO5)

CO-PO Mapping

	PP3				
CO	PO1	PO2	PO3	PO4	PO5
CO1			2		1
CO2			2		1
CO3			2		1
CO4			2		1
CO5			2		1

UNIT - I

Introduction to C-based FPGA Design, Using Vivado HLS HLS UltraFast Design Methodology Managing Interfaces Design Optimization RTL Verification, Exporting the RTL Design

UNIT - II

Introduction to the Vivado HLS C Libraries, Arbitrary Precision Data Types Library, The HLS Stream Library, HLS Math Library, Vivado HLS Video Library, The HLS IP Libraries, HLS Linear Algebra Library.

UNIT - III

Coding Styles: Unsupported C Constructs, The C Test Bench Functions, Loops, Arrays, Data Types. C++ Classes and Templates, Using Assertions, SystemC Synthesis.

UNIT - IV

Command Reference, Graphical User Interface (GUI) Reference, Send Feedback, Interface Synthesis Reference, AXI4 Slave Lite C Driver Reference, Video Functions Reference.

UNIT - V

HLS Linear Algebra Library, C Arbitrary Precision Types, C++ Arbitrary Precision Types, C++ Arbitrary Precision Fixed Point Types, Comparison of SystemC and Vivado HLS Types.

Learning Resources:

- 2. Andres Takach, Creating C++ IP for High Performance Hardware Implementations of FFTs. DesignsDesignCon2002.
- 3. Preston A. Jackson, Cy P. Chan, Jonathan E. Scalera, Charles M. Rader, and M. Michael Vai A Systolic FFT Architecture for Real Time FPGA Systems. MIT Lincoln Laboratory 244 Wood ST, Lexington, MA 02420
- Vivado Design Suite User Guide and Vivado Design Suite Tutorial for High-Level Synthesis.

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DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Low Power VLSI Design

Professional Elective - IV
SYLLABUS FOR M.E. ECE (ES&VLSID) - III SEMESTER

L:T:P(Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P25PE320EC
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

COURSE OBJECTIVES COURSE OUTCOMES 1. Study different abstraction levels On completion of the course, students will be able to in VLSI Design and the impact of 1. Distinguish the impact of various power reduction techniques at different levels of VLSI Design power reduction methods at higher levels 2. Identify the sources of power dissipation and apply leakage control techniques to reduce static power 2. Apply leakage control mechanisms consumption in CMOS circuits reduce static power consumption in DSM VLSI regime 3. Apply technology independent and technology-3. Apply technology independent and dependent techniques for Dynamic technology-dependent techniques reduction in CMOS circuits for Dynamic power reduction in 4. Analyze different power reduction techniques for CMOS circuits VLSI systems at Design time, Run-time and Stand-4. Study and apply various software by modes 5. Employ power estimation and optimization software power estimation techniques for low power VLSI optimization methods for low power VLSI system system design 5. Apply low power circuit and 6. Apply low power circuit and architectural techniques such as capacitance reduction, gated architectural techniques for clocking, VDD and Vth scaling, DVS etc in digital reducing power consumption in SRAM designs systems and SRAM designs CO-PO Mapping

CO	PO1	PO2	PO3	PO4	PO5
CO1			2		1
CO2			2		1
CO3			2		1
CO4			2		1
CO5			2		1

UNIT - I

Introduction to Low Power design: Why worry about power – at global and SOC levels, Emerging zero-power applications (WSN), 20 nm scenario, Design-productivity challenge, Impact of implementation choices, Motivation for LPD, Basic VLSI Design Flow, Optimization examples at various levels (System, Subsystem, RTL, Gate, Circuit and Device levels)

Sources of power dissipation, MOS transistor leakage components, Static Power dissipation, Active Power dissipation, Circuit Techniques for Low Power Design – Standby leakage control using transistor stacks, Multiple V_{TH} and dynamic V_{TH} techniques, Supply voltage scaling technique (Ref-1)

UNIT - II

Power Optimization Techniques – I: Dynamic Power Reduction Approaches, Circuit Parallelization, Voltage Scaling Based Circuit Techniques, Circuit Technology – Independent Power Reduction, Circuit Technology Dependent Power Reduction; Leakage Power Reduction – Leakage Components, Design Time Reduction Techniques, Run-time Stand-by Reduction Techniques, Run-time Active Reduction Techniques Reduction in Cache Memories (Ref-2)

UNIT - III

Power Optimization Techniques – II: Energy Recovery Circuit Design, Adiabatic – Charging Principle and its implementation issues (Ref-2) Software Design for Low Power: Sources of Software Power Dissipation, Software Power Estimation, Software Power Optimizations, Automated Low-Power Code Generation, Co-design for Low Power (Ref-3)

UNIT - IV

Low Voltage Low Power Static Random Access memories: Basics, Race between 6T and 4T memory cells, LVLP SRAM Cell designs- Shared bit-line SRAM cell configuration, Power efficient 7T SRAM cell with current mode read and write, Loadless CMOS 4T SRAM cell, The 1T SRAM cell, Pre-charge and Equalization Circuit, Dynamic and static decoders, Voltage Sense amplifier, Output Latch, Low Power SRAM Techniques: Sources of SRAM Power, Low Power Circuit techniques such as capacitance reduction, Leakage current reduction (Ref-1)

UNIT - V

Large LP VLSI System design and Applications: Architecture-driven Voltage Scaling, Power optimization using operation reduction and operation substitution, Pre-computation based optimization, Multiple and Dynamic supply voltage design, Choice of supply voltages, Varying the clock speed, varying the V_{DD} of RAM structures, Gated Clocking. Leakage current reduction in medical devices (Ref-1)

Learning Resources:

- Kiat-Seng Yeo and Kaushik Roy, "Low-Voltage, Low-Power VLSI Subsystems, Tata McGrawhill Edition, 2005. (Units I, IV and V)
- 2. Christian Piguet, "Low Power CMOS Circuits Technology, Logic Design and CAD Tools", 1st Indian Reprint, CRC Press, 2010.(Units II and III)
- 3. Kaushik Roy and Sharat Prasad, "Low-Power CMOS VLSI Circuit Design", Wiley Pub., 2000 (Unit III)
- 4. Dimitrios Soudris, Christian Piguet and Coastas Goutis, "Designing CMOS Circuits for Low Power", Kluwer Academic Pub, 2002 (Topics beyond Syllabus)
- 5. J. Rabaey, Low Power Design Essentials, 1st Edition, Springer Publications, 2010 (for seminars and assignments)

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DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

System on Chip (SoC) Design

Professional Elective - IV
SYLLABUS FOR M.E. ECE (ES&VLSID) - III SEMESTER

L:T:P (Hrs./week) : 3:0:0	SEE Marks: 60	Course Code: P25PE330EC
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

COURSE OBJECTIVES	COURSE OUTCOMES
This course covers the advanced design and analysis of digital circuits with HDL. The primary goal is to provide in depth understanding of system design. The course enables students to apply their knowledge for the design of advanced digital hardware systems with help of FPGA tools. 1. Understand the FPGA hardware architecture and interconnect technologies. 2. Apply the knowledge for the design of digital hardware systems. 3. Implementation of FPGA implementation methodologies with the help of FPGA tools. 4. Block level design verification by writing the test benches. 5. System level design verification by writing the test cases.	On completion of the course, students will be able to 1. Understand design flow of SoC 2. Implement the basic level logic functions in hardware system. 3. Implement the block level and system level IP cores. 4. Writing test benches for block level design verification. 5. Writing test benches for system level design verification.

UNIT - I

Introduction to SoC Design, constituents of SoC, Application areas of SoC, SoC development life cycle FPGA architectures for implementing SoC design, FPGA based SoC design flow.

UNIT - II

Front End Design and Back-End Design Overview, Programmable system on chip design, Design with Xilinx zynq SoC platform, Implementation examples of logic functions using LUTs and CLBs, Finite state machine design examples.

UNIT - III

Introduction to IP cores, Block level design using IP cores, Implementation of Block RAM using IP cores, FIFO design and implementation using IP cores.

UNIT - IV

Block Level Design Verification: Introduction to Block-level verification, verification approaches, Functional verification, Static timing verification, Front End Design stages in detail-Flow: Architecture, Design Entry, Simulation, Synthesis and Verification, 16 bit ALU design verification with VIO hardware debugger, Constraints and timings analysis.

UNIT-V

System Level Design Verification: Introduction to system level verification, creating system-level test benches, Applying and migrating test bench-SoC, Design challenges and approaches.

Learning Resources:

- 1. Veena S. Chakravarthi, "A practical Approach to VLSI System on Chip (SoC) Design", A comprehensive Guide, Springer.
- 2. Prakash Rashinkar, Peter Paterson and Leena Singh "System-on-a-Chip Verification Methodology and Techniques", Kluwer Academic Publishers.

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VASAVI COLLEGE OF ENGINEERING (AUTONOMOUS) ACCREDITED BY NAAC WITH 'A++' GRADE IBRAHIMBAGH, HYDERABAD – 500 031

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

IoT Architectures and Applications

(Professional Elective-V)
SYLLABUS FOR M.E. III – SEMESTER

L:T:P (Hrs./week) : 3:0:0 SEE Marks : 60 Course Code: **P25PE340EC**Credits : 3 CIE Marks : 40 Duration of SEE : 3 Hours

COURSE OBJECTIVES	COURSE OUTCOMES
	On completion of the course, students will be able to
to impart knowledge on IoT	Understand the Architectural Overview of IoT
Architecture, practical	2. Enumerate the need and the challenges in Real
constrains, various protocols	World Design Constraints
and multiple case studies.	3. Choose the required protocol for a given application.
-	4. Explore IoT usage in various applications
	5. Understand the Security requirements in IoT.

CO-PO Mapping

	~				
CO	PO1	PO2	PO3	PO4	PO5
CO1			3		
CO2			3		
CO3			3		
CO4			3		
CO5			3		

UNIT - I : IoT

Definition and Technologies that led to evolution of IOT, Characteristics of IoT, Physical Design of IoT, Logical Design of IoT, IoT Enabling Technologies, IoT Levels & Deployment. M2M and IoT Technology Fundamentals- Devices and gateways, Introduction to cloud IOT platforms like MS Azure, AWS IOT, Google Cloud IOT, Thingworx, Business processes in IoT.

UNIT - II : IoT Reference Architecture

Introduction, Functional View, Information View, Deployment and Operational View, Other Relevant architectural views. IoT edge system architecture.

Real-World Design Constraints: Technical Design constraints, Connectivity constraints, Data representation and visualization, Big Data Management.

UNIT - III : IoT communications

Data link and physical layer Protocols: PHY/MAC Layer (IEEE 802.11, IEEE 802.15), Bluetooth Low Energy, Thread, introduction to Wi-SUN.

Network Layer Protocols: IPv6, 6LoWPAN;

Transport layer protocols: TCP, UDP;

Messaging protocols: Quality of services in MQTT, standards and security in MQTT, CoAP, AMQP.

UNIT - IV : Case Studies

Smart Cities, Smart Homes, Smart Transportation, Smart Healthcare, Precision Agriculture, Connected Vehicles.

IOT in Indian Scenario: i) IOT and Aadhaar ii) IOT for health services. iii) IOT for financial inclusion. iv) IOT for rural empowerment v) India Urban Data Exchange (IUDX).

Industry 4.0: Industrial Internet of Things (IIoT), Reference Architecture, Characteristics of Industry 4.0.

UNIT - V : Securing the Internet of Things

Security Requirements in IoT Architecture - Security in Enabling Technologies, Security Concerns in IoT Applications.

Security Architecture in the Internet of Things - Security Requirements in IoT, Insufficient Authentication/Authorization, Insecure Access Control, Threats to Access Control, Privacy, and Availability, Attacks Specific to IoT. Security and Vulnerabilities - Secrecy & Secret Key Capacity, Authentication/Authorization for Smart Devices, Transport Encryption, Secure Cloud/Web Interface, Secure Software/Firmware, Physical Layer Security.

Learning Resources:

- 1 Pethuru Raj and Anupama C. Raman, —The Internet of Things: Enabling Technologies, Platforms, and Use Cases", 1st Edition, 2017, CRC Press.
- 2 David Hanes, Gonzalo Salgueiro, Patrick Grossetete, Rob Barton, Jerome Henny "IoT Fundamentals: Networking technologies Protocols, and Use Cases for the internet of things", June, 2017, Cisco press.
- 3 Jan Holler, VlasiosTsiatsis, Catherine Mulligan, Stefan Avesand, Stamatis Karnouskos, David Boyle, —From Machine-to-Machine to the Internet of Things: Introduction to a New Age of Intelligence||, 1st Edition, 2014, Academic Press.
- 4 Arshdeep Bahga, Vijay Madisetti, —Internet of Things: A Hands-on Approach||, Universities Press, 2014.
- 5 Practical Internet of Things Security (Kindle Edition) by Brian Russell, Drew Van Duren, Packt Publishing, 2016.
- 6 Securing the Internet of Things Elsevier Authors: Shancang Li Li Da Xu,Paperback ISBN: 9780128044582,Imprint: SyngressPublished Date: 13th January 2017.
- 7 https://nptel.ac.in/courses/106105166/5
- 8 https://nptel.ac.in/courses/108108098/4

The break-up of CIE: Internal Tests + Assignments + Quizzes

1. No. of Internal Tests : 2 Max. Marks for each Internal Test : 30

2. No. of Assignments : 3 Max. Marks for each Assignment : 5

3. No. of Quizzes : 3 Max. Marks for each Quiz Test : 5

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Physical Design Automation

Professional Elective - V SYLLABUS FOR M.E. ECE (ES&VLSID) - III SEMESTER

L:T:P (Hrs./week) : 3:0:0	SEE Marks: 60	Course Code: P25PE350EC
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

COURSE OBJECTIVES	COURSE OUTCOMES
Students will develop placement and routing algorithms for VLSI Designs using C / C++.	On completion of the course, students will be able to 1. understand the relationship between design automation algorithms and various constraints posed by VLSI fabrication and design technology. 2. adapt the design algorithms to meet the critical design parameters. 3. map various layout optimization techniques to the algorithms. 4. develop proto-type EDA tool and test its efficacy.

CO-PO Manning

CO-PO I	rapping				
CO	PO1	PO2	PO3	PO4	PO5
CO1			2		1
CO2			2		1
CO3			2		1
CO4			2		1

UNIT-I: VLSI design Cycle, Physical Design Cycle, Design Rules, Layout of Basic Devices, and Additional Fabrication, Design styles: full custom, standard cell, gate arrays, field programmable gate arrays, sea of gates and comparison, system packaging styles, multi chip modules. Design rules, layout of basic devices, fabrication process and its impact on physical design, interconnect delay, noise and cross talk, yield and fabrication cost. Factors,

UNIT-II: Complexity Issues and NP-hard Problems, Basic Algorithms (Graph and

Computational Geometry): graph search algorithms, spanning tree algorithms, shortest path algorithms, matching algorithms, min-cut and max-cut algorithms, Steiner tree algorithms.

UNIT-III: Basic Data Structures, atomic operations for layout editors, linked list of blocks, bin based methods, neighbour pointers, corner stitching, multi-layer operations.

UNIT-IV: Graph algorithms for physical design: classes of graphs, graphs related to a set of lines, graphs related to set of rectangles, graph problems in physical design, maximum clique and minimum coloring, maximum k-independent set algorithm, algorithms for circle graphs.

UNIT-V: Partitioning algorithms: design style specific partitioning problems, group migrated algorithms, simulated annealing and evolution, and Floor planning and pin assignment, Routing and placement algorithms.

Learning Resources:

- 1. Naveed Shervani, Algorithms for VLSI Physical Design Automation, 3rd Edition, Kluwer Academic, 1999.
- 2. Charles J Alpert, Dinesh P Mehta, Sachin S Sapatnekar, Handbook of Algorithms for Physical Design Automation, CRC Press, 2008

The break-up of CIE : Internal Tests + Assignments + Quizzes

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3. No. of Quizzes : 3 Max. Marks for each Quiz Test : 5

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Design for Testability

Professional Elective - V SYLLABUS FOR M.E. ECE (ES&VLSID) - III SEMESTER

L:T:P(Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P25PE360EC
Credits: 3	CIE Marks: 40	Duration of SEE : 3 Hours

COURSE OBJECTIVES	COURSE OUTCOMES
To expose the students, the basics of testing techniques for circuits.	On completion of the course, students will be able to 1. Illustrate Yield, Fabrication defects, Errors and Faults in VLSI Circuits 2. Simulate digital ICs in the presence of faults and evaluate the given test set for fault coverage. 3. Generate test patterns for detecting single stuck faults in combinational and sequential circuits. 4. Establish a fault model for memory and apply March Tests for fault detection 5. Identify schemes for introducing testability into digital circuits with improved fault coverage. 6. Compare different approaches for introducing BIST into
	logic circuits, memories and embedded cores.

CO-PO Mapping

	.~pp9				
CO	PO1	PO2	PO3	PO4	PO5
CO1			2		1
CO2			2		1
CO3			2		1
CO4			2		1
CO5			2		1

UNIT - I

Introduction: Role of Testing, Digital and Analog VLSI Testing, The Rule of TEN, Yield, Defects and Faults, Reliability and Failure Rate, Test and Design for Testability (DFT)

Modeling: Modeling digital circuits at logic level, register level and structural models.

Logic Simulation: Types of simulation, Delay models, Element evaluation, Hazard detection, Gate level event- driven simulation. {Ref1: Chs 1,2,3 and Ref2: Ch3)

UNIT - II

Fault Modeling – Logic fault models, Fault detection and redundancy, Fault equivalence, Fault location and Fault Collapsing, The Single Stuck and Multiple

Stuck Fault Models. Bridging Faults, CMOS Technology Considerations, Intermittent Faults

Fault Simulation: Applications, Fault Simulation for Combinational circuits. (Ref1: Chs 4 and 5)

UNIT - III

Testing for single stuck faults (SSF): Automated Test Pattern Generation (ATPG/ATG) for SSFs in Combinational Circuits, Algorithms (D, PODEM, FAN), ATG for SSFs in Sequential Circuits. Functional Testing without and with Specific Fault Models

Memory Test: Memory density and Defect trends, Faults, Memory Test levels, March Test Notation, Fault Modeling, Memory Testing {Ref1: Chs 6 and 8, Ref2: Ch 9)

UNIT - IV

Design for Testability – Controllability and Observability, AdHoc DFT techniques. Scan architectures and testing – Generic boundary scan, Full Serial integrated scan, Storage cells for scan design. Board level and system level DFT approaches. Boundary scan standards. Compression techniques – Syndrome test and Signature analysis – LFSR based Signature Analysis (Ref1: Chs 9 and 10)

UNIT - V

Built-in Self-Test (BIST) – BIST Concepts and test pattern generation. Specific BIST Architectures in brief.

System Test and Core-Based Design: System Test Problem Defined, Functional Test, Diagnostic Test, Testable System design, Core-Based Design and Test –Wrapper, A Test Architecture for SOC, An Integrated Design and Test Approach. {Ref1: Ch 11, Ref2: Ch 18}

DSP-based Analog and Mixed-Signal Test: Functional DSP-based Testing, Static ADC/DAC Testing Methods, CODEC Testing, Dynamic Flash ADC Testing using FFT Technique. {Ref2: Ch 10}.

Learning Resources:

- 1. Miron Abramovici, Melvin A. Breur, Arthur D. Friedman, "Digital Systems Testing and Testable Design", Jaico Publishing House, 2001.
- 2. Michael L Bushnell and Vishwani D Agrawal, "Essentials of Electronic Testing for Digital, Memory and Mixed Signal VLSI Circuits" Kluwer Academic Publishers, 2002
- 3. NPTEL Course on VLSI Testing IIT Kharagpur

The break-up of CIE: Internal Tests + Assignments + Quizzes

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3. No. of Quizzes : 3 Max. Marks for each Quiz Test : 5

DEAPRTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Dissertation - Phase - I / Internship

SYLLABUS FOR M.E. ECE (ES&VLSID) - III SEMESTER

L:T:P(Hrs./week): 0:0:20	SEE Marks: -	Course Code: P25PW319EC
Credits: 10	CIE Marks: 100	Duration of SEE : -

COURSE OBJECTIVES	COURSE OUTCOMES
Prepare the student for a systematic and	On completion of the course, students will
independent study of the state of the art	be able to
topics in a broad area of his/her specialization	To select the complex engineering problems beneficial to the society and develop solutions with appropriate considerations in the area of VLSI and embedded systems.
	To apply modern tools and analyze the results to provide valid conclusions.
	To communicate effectively the solutions with report and presentation following ethics
	4. To adapt for the advanced technological changes
	5. To work in teams and apply management principles to complete the project economically
	the project economically

CO-PO Mapping

CO-FO Mapping					
СО	PO1	PO2	PO3	PO4	PO5
CO1	2	2			
CO2				3	
CO3			2		
CO4			2		
CO5					3

The students must be given clear guidelines to execute and complete the project on which they have delivered a seminar in the 3rd semester of the course.

All projects will be monitored at least twice in a semester through student's presentation. Sessional marks should be based on the grades/marks, awarded by a monitoring committee of faculty members as also marks given by the supervisor.

Efforts be made that some of the projects are carries out in industries with the help of industry support.

The final project reports must be submitted two weeks before the last working day of the semester.

The project works must be evaluated by departmental committee containing of HOD, two senior faculty and supervisor.

Continuous Internal Evaluation (CIE) – 100 marks:

Evaluation Criteria	Maximum Marks
Literature Survey	20
Problem Formulation	20
Design/ Methodology	20
Implementation & Results	20
Presentation & Documentation	20

Note: Rubrics are used for assessment and evaluation.

Syllabus for M.E. ECE (ES & VLSI Design) IV - Semester

DEAPRTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Dissertation - Phase - II / Internship

SYLLABUS FOR M.E. ECE (ES&VLSID) - IV SEMESTER

L:T:P(Hrs./week):0:0:32	SEE Marks: -	Course Code:	P25PW419EC
Credits: 16	CIE Marks: Viva	-Voce Grade	Duration of SEE:

COURSE OBJECTIVES	COURSE OUTCOMES
Prepare the student for a systematic and independent study of the state of the art topics in a broad area of	On completion of the course, students will be able to 1. To select the complex engineering problems beneficial to the society and develop solutions with appropriate considerations in the area of VLSI and
his/her specialization	embedded systems. 2. To apply modern tools and analyze the results to provide valid conclusions.
	To communicate effectively the solutions with report and presentation following ethics
	4. To adapt for the advanced technological changes 5. To work in teams and apply management principles
	to complete the project economically

CO-PO Mapping

	.~PP9				
СО	PO1	PO2	PO3	PO4	PO5
CO1	2	2			
CO2				3	
CO3			2		
CO4			2		
CO5					3

The students must be given clear guidelines to execute and complete the project on which they have delivered a seminar in the 3rd semester of the course.

All projects will be monitored at least twice in a semester through student's presentation. Sessional marks should be based on the grades/marks, awarded by a monitoring committee of faculty members as also marks given by the supervisor.

Efforts be made that some of the projects are carries out in industries with the help of industry coordinates.

Common norms will be established for documentation of the project report by the respective department.

The final project reports must be submitted two weeks before the last working day of the semester.

The project works must be evaluated by an external examiner and based on his comments a viva voice will be conducted by the departmental committee containing of HOD, two senior faculty and supervisor.

Criteria for Award of Grades:

Academic Performance (%)	Letter Grade	Grade Points
90 to 100	A+ (Outstanding)	10
80 to < 90	A (Excellent)	09
70 to < 80	B+ (Very Good)	08
60 to < 70	B (Good)	07
50 to < 60	C (Average)	06
< 50	F (Fail)	0

Note: Following criteria used for assessment and evaluation.

QUA	QUALITY		
1.	Review of literature	()
2.	Scope of the work	()
3.	Technical soundness (Methodology / Experimental set-up)	()
4.	Timeliness of work	()
5.	Conclusions drawn	()
CON	TENT		
6.	Adequacy of data, information and Practical applications / utility	()
7.	Organization of the thesis	()
PRES	SENTATION		
8.	Clear explanation of the work	()
9.	Justification of work done	()
10.	Clarity and unambiguity of the language	()
	Total Score out of 100	()
(in words)			

Open Electives

DEAPRTMENT OF HUMANITIES AND SOCIAL SCIENCES

Business Analytics

Open Elective

SYLLABUS FOR M.E. - II SEMESTER

L:T:P(Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P250E210XX
Credits: 3	CIE Marks: 40	Duration of SEE : 3 Hours

	COURSE OBJECTIVES	COURSE OUTCOMES
1.	Understand the role of business analytics within	On completion of the course,
	an organization.	students will be able to
2.	Analyze data using statistical and data mining	1. Students will demonstrate
	techniques and understand relationships between	knowledge of data
	the underlying business processes of an	analytics.
_	organization.	2. Students will demonstrate
3.	To gain an understanding of how managers use	the ability of think critically
	business analytics to formulate and solve	in making decisions based on data and deep
	business problems and to support managerial decision making.	on data and deep analytics.
4	To become familiar with processes needed to	Students will demonstrate
"	develop, report, and analyze business data.	the ability to use technical
5.	Use decision-making tools/Operations research	skills in predicative and
	techniques.	prescriptive modeling to
6.	Mange business process using analytical and	support business decision-
	management tools.	making.
7.	Analyze and solve problems from different	4. Students will demonstrate
	industries such as manufacturing, service, retail,	the ability to translate data
	software, banking and finance, sports,	into clear, actionable
	pharmaceutical, aerospace etc.	insights

UNIT -I

Business analytics: Overview of Business analytics, Scope of Business analytics, Business Analytics Process, Relationship of Business Analytics Process and organisation, competitive advantages of Business Analytics. Statistical Tools: Statistical Notation, Descriptive Statistical methods, Review of probability distribution and data modelling, sampling and estimation methods overview.

UNIT - II

Trendiness and Regression Analysis: Modelling Relationships and Trends in Data, simple Linear Regression. Important Resources, Business

Analytics Personnel, Data and models for Business analytics, problem solving, Visualizing and Exploring Data, Business Analytics Technology.

UNIT - III

Organization Structures of Business analytics, Team management, Management Issues, Designing Information Policy, Outsourcing, Ensuring Data Quality, Measuring contribution of Business analytics, Managing Changes. Descriptive Analytics, predictive analytics, predictive Modelling, Predictive analytics analysis, Data Mining, Data Mining Methodologies, Prescriptive analytics and its step in the business analytics Process, Prescriptive Modelling, nonlinear Optimization

UNIT - IV

Forecasting Techniques: Qualitative and Judgmental Forecasting, Statistical Forecasting Models, Forecasting Models for Stationary Time Series, Forecasting Models for Time Series with a Linear Trend, Forecasting Time Series with Seasonality, Regression Forecasting with Casual Variables, Selecting Appropriate Forecasting Models. Monte Carlo Simulation and Risk Analysis: Monte Carle Simulation Using Analytic Solver Platform, New-Product Development Model, Newsvendor Model, Overbooking Model, Cash Budget Model.

UNIT - V

Decision Analysis: Formulating Decision Problems, Decision Strategies with the without Outcome Probabilities, Decision Trees, The Value of Information, Utility and Decision Making.

UNIT - VI

Recent Trends in: Embedded and collaborative business intelligence, Visual data recovery, Data Storytelling and Data journalism.

Learning Resources:

- Business analytics Principles, Concepts, and Applications by Marc J. Schniederjans, Dara G. Schniederjans, Christopher M. Starkey, Pearson FT Press.
- 2. Business Analytics by James Evans, persons Education.

The break-up of CIE : Internal Tests + Assignments + Quizzes

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DEAPRTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Industrial Safety

Open Elective SYLLABUS FOR M.E. - II SEMESTER

L:T:P(Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P250E220XX
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

UNIT - I

Industrial safety: Accident, causes, types, results and control, mechanical and electrical hazards, types, causes and preventive steps/procedure, describe salient points of factories act 1948 for health and safety, wash rooms, drinking water layouts, light, cleanliness, fire, guarding, pressure vessels, etc, Safety color codes. Fire prevention and firefighting, equipment and methods.

UNIT - II

Fundamentals of maintenance engineering: Definition and aim of maintenance engineering, Primary and secondary functions and responsibility of maintenance department, Types of maintenance, Types and applications of tools used for maintenance, Maintenance cost & its relation with replacement economy, Service life of equipment. Model Curriculum of Engineering & Technology PG Courses [Volume -II] 295

UNIT - III

Wear and Corrosion and their prevention: Wear- types, causes, effects, wear reduction methods, lubricants-types and applications, Lubrication methods, general sketch, working and applications, i. Screw down grease cup, ii. Pressure grease gun, iii. Splash lubrication, iv. Gravity lubrication, v. Wick feed lubrication vi. Side feed lubrication, vii. Ring lubrication, Definition, principle and factors affecting the corrosion. Types of corrosion, corrosion prevention methods.

UNIT - IV

Fault tracing: Fault tracing-concept and importance, decision treeconcept, need and applications, sequence of fault finding activities, show as decision tree, draw decision tree for problems in machine tools, hydraulic, pneumatic, automotive, thermal and electrical equipment's like, I. Any one machine tool, ii. Pump iii. Air compressor, iv. Internal combustion engine,

v. Boiler, vi. Electrical motors, Types of faults in machine tools and their general causes.

UNIT - V

Periodic and preventive maintenance: Periodic inspection-concept and need, degreasing, cleaning and repairing schemes, overhauling of mechanical components, overhauling of electrical motor, common troubles and remedies of electric motor, repair complexities and its use, definition, need, steps and advantages of preventive maintenance. Steps/procedure for periodic and preventive maintenance of: I. Machine tools, ii. Pumps, iii. Air compressors, iv. Diesel generating (DG) sets, Program and schedule of preventive maintenance of mechanical and electrical equipment, advantages of preventive maintenance. Repair cycle concept and importance

Learning Resources:

- Maintenance Engineering Handbook, Higgins & Morrow, Da Information Services.
- 2. Maintenance Engineering, H. P. Garg, S. Chand and Company.
- 3. Pump-hydraulic Compressors, Audels, Mcgrew Hill Publication.
- 4. Foundation Engineering Handbook, Winterkorn, Hans, Chapman & Hall London.

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DEPARTMENT OF MECHANICAL ENGINEERING

Operations Research

Open Elective
SYLLABUS FOR M.E. II SEMESTER

L:T:P(Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P250E230XX	
Credits: 3	CIE Marks: 40	Duration of SEE : 3 Hours	

COURSE OBJECTIVES	COURSE OUTCOMES
The objective of this course is to:	On completion of the course, the student will be able to:
understand Linear & non- linear programming, transportation modelling, CPM & PERT for project scheduling and control, replacement, game theory and sequencing	 understand simplex, dual simplex, Sensitivity and transportation and their applications for shop floor problems. understand the importance of Sensitivity analysis and various advanced LPP techniques apply the techniques like CPM and PERT for project management. apply various replacement techniques to find optimum replacement time period for equipment. identify the best strategy to win the game and
	optimum sequence for minimum elapsed time.

UNIT-I: OPERATIONS RESEARCH-AN OVERVIEW

Meaning and Origin of Operations research, Introduction to Linear programming problems (LPP) -Formulation of LPP-Solution to LPP by Graphical method and simplex method.

UNIT-II: ADVANCED TOPICS IN LINEAR PROGRAMMING

Dual simplex method, special cases in LPP, Duality in LPP, Differences between primal and dual, shadow prices, sensitivity analysis. Non linear programming Khun Tucker conditions.

UNIT-III

Transportation Model: Definition of the transportation model-matrix of Transportation model-Formulation and solution of transportation models-Methods for calculating Initial basic feasible solution, optimal solution by Stepping stone method and MODI method.

Assignment Problem: Hungarian method of assignment problem, maximization in assignment problem, unbalanced problem, problems with restrictions, travelling salesman problems.

UNIT-IV: PROJECT SCHEDULING

Introduction to network analysis, Rules to draw network diagram, Fulkerson rule for numbering events, Critical path method, Summarisation of CPM calculations. PERT, Estimation of probability and its corresponding duration in PERT, Crashing of project and finding of optimal project duration in crashing.

UNIT-V

Replacement models: Introduction, replacement of items that deteriorate ignoring change in money value, replacement of items that deteriorate considering change in money value with time, replacement of items that fail suddenly – individual replacement policy, group replacement policy.

Game theory: Introduction, 2 person zero sum games, maximi— minima principle, principle of dominance, solution for mixed strategy problems graphical method for $2 \times n$ and $m \times 2$ games

Sequencing models: introduction, general assumptions, processing to jobs through 2 machines, processing 'n' jobs through m machines processing 2 jobs through m machines.

Learning Resources:

- S. D.Sharma, "Operations Research", 10th edition, Newage India Pvt Ltd, New Delhi
- 2. Hamady.A.Taha An Introduction to Operations Research, "8th edition, TMH
- Prem Kumar Gupta and Dr. DS Hira, "Operations Research ", S.Chand & Company Pvt. Ltd., 2014.
- 4. R. Paneerselvam, "Operations Research", PHI Learning Pvt Ltd., 2009.
- NVS Raju, "Optimization methods for Engineers", PHI Learning Pvt. Ltd. ., 2014
- Col D.S. Cheema, "Operations Research", University science press, 2nd edition, India

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DEAPRTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Cost Management of Engineering Projects

Open Elective SYLLABUS FOR M.E. - II SEMESTER

L:T:P(Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P250E240XX	
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours	

Introduction and Overview of the Strategic Cost Management Process Cost concepts in decision-making; Relevant cost, Differential cost, Incremental cost and Opportunity cost. Objectives of a Costing System; Inventory valuation; Creation of a Database for operational control; Provision of data for Decision-Making.

Project: meaning, Different types, why to manage, cost overruns centres, various stages of project execution: conception to commissioning. Project execution as conglomeration of technical and nontechnical activities. Detailed Engineering activities. Pre project execution main clearances and documents Project team: Role of each member. Importance Project site: Data required with significance. Project contracts. Types and contents. Project execution Project cost control. Bar charts and Network diagram. Project commissioning: mechanical and process

Cost Behavior and Profit Planning Marginal Costing; Distinction between Marginal Costing and Absorption Costing; Break-even Analysis, Cost-Volume-Profit Analysis. Various decision-making problems. Standard Costing and Variance Analysis. Pricing strategies: Pareto Analysis. Target costing, Life Cycle Costing. Costing of service sector. Just-in-time approach, Material Requirement Planning, Enterprise Resource Planning, Total Quality Management and Theory of constraints. Activity-Based Cost Management, Bench Marking; Balanced Score Card and Value-Chain Analysis. Budgetary Control; Flexible Budgets; Performance budgets; Zero-based budgets. Measurement of Divisional profitability pricing decisions including transfer pricing.

Quantitative techniques for cost management, Linear Programming, PERT/CPM, Transportation problems, Assignment problems, Simulation, Learning Curve Theory.

Learning Resources:

- 1. Cost Accounting A Managerial Emphasis, Prentice Hall of India, New Delhi
- 2. Charles T. Horngren and George Foster, Advanced Management Accounting
- 3. Robert S Kaplan Anthony A. Alkinson, Management & Cost Accounting
- 4. Ashish K. Bhattacharya, Principles & Practices of Cost Accounting A. H. Wheeler publisher
- N.D. Vohra, Quantitative Techniques in Management, Tata McGraw Hill Book Co. Ltd.

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DEAPRTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Composite Materials

Open Elective
SYLLABUS FOR M.E. - II SEMESTER

L:T:P(Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P250E250XX
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

UNIT-I

INTRODUCTION: Definition – Classification and characteristics of Composite materials. Advantages and application of composites. Functional requirements of reinforcement and matrix. Effect of reinforcement (size, shape, distribution, volume fraction) on overall composite performance.

UNIT - II

REINFORCEMENTS: Preparation-layup, curing, properties and applications of glass fibers, carbon fibers, Kevlar fibers and Boron fibers. Properties and applications of whiskers, particle reinforcements. Mechanical Behavior of composites: Rule of mixtures, Inverse rule of mixtures. Isostrain and Isostress conditions.

UNIT - III

Manufacturing of Metal Matrix Composites: Casting – Solid State diffusion technique, Cladding – Hot isostatic pressing. Properties and applications. Manufacturing of Ceramic Matrix Composites: Liquid Metal Infiltration – Liquid phase sintering. Manufacturing of Carbon – Carbon composites: Knitting, Braiding, Weaving. Properties and applications.

UNIT-IV

Manufacturing of Polymer Matrix Composites: Preparation of Moulding compounds and prepregs – hand layup method – Autoclave method – Filament winding method – Compression moulding – Reaction injection moulding. Properties and applications.

UNIT - V

Strength: Laminar Failure Criteria-strength ratio, maximum stress criteria, maximum strain criteria, interacting failure criteria, hygrothermal failure. Laminate first play failure-insight strength; Laminate strength-ply discount

truncated maximum strain criterion; strength design using caplet plots; stress concentrations.

Learning Resources:

- Material Science and Technology Vol 13 Composites by R.W.Cahn VCH, West Germany.
- 2. Materials Science and Engineering, An introduction. WD Callister, Jr., Adapted by R. Balasubramaniam, John Wiley & Sons, NY, Indian edition, 2007.
- 3. Hand Book of Composite Materials-ed-Lubin.
- 4. Composite Materials K.K.Chawla.
- 5. Composite Materials Science and Applications Deborah D.L. Chung.
- 6. Composite Materials Design and Applications Danial Gay, Suong V. Hoa, and Stephen W. Tasi.

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1. No. of Internal Tests : 2 Max. Marks for each Internal Tests : 30

2. No. of Assignments : 3 Max. Marks for each Assignment : 5

3. No. of Quizzes : 3 Max. Marks for each Quiz Test : 5

DEAPRTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Waste to Energy

Open Elective

SYLLABUS FOR M.E. ECE (ES&VLSID) - II SEMESTER

L:T:P(Hrs./week): 3:0:0	SEE Marks: 60	Course Code: P250E260XX
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

UNIT-I

Introduction to Energy from Waste: Classification of waste as fuel – Agro based, Forest residue, Industrial waste - MSW – Conversion devices – Incinerators, gasifiers, digestors

UNIT - II

Biomass Pyrolysis: Pyrolysis – Types, slow fast – Manufacture of charcoal – Methods - Yields and application – Manufacture of pyrolytic oils and gases, yields and applications.

UNIT - III

Biomass Gasification: Gasifiers – Fixed bed system – Downdraft and updraft gasifiers – Fluidized bed gasifiers – Design, construction and operation – Gasifier burner arrangement for Model Curriculum of Engineering & Technology PG Courses [Volume -II] 299 thermal heating – Gasifier engine arrangement and electrical power – Equilibrium and kinetic consideration in gasifier operation.

UNIT - IV

Biomass Combustion: Biomass stoves – Improved chullahs, types, some exotic designs, Fixed bed combustors, Types, inclined grate combustors, Fluidized bed combustors, Design, construction and operation - Operation of all the above biomass combustors.

UNIT - V

Biogas: Properties of biogas (Calorific value and composition) - Biogas plant technology and status - Bio energy system - Design and constructional features - Biomass resources and their classification - Biomass conversion processes - Thermo chemical conversion - Direct combustion - biomass gasification - pyrolysis and liquefaction - biochemical conversion - anaerobic digestion - Types of biogas Plants -

Applications - Alcohol production from biomass - Bio diesel production - Urban waste to energy conversion - Biomass energy programme in India.

Learning Resources:

- 1. Non Conventional Energy, Desai, Ashok V., Wiley Eastern Ltd., 1990.
- 2. Biogas Technology A Practical Hand Book Khandelwal, K. C. and Mahdi, S. S., Vol. I & II, Tata McGraw Hill Publishing Co. Ltd., 1983.
- 3. Food, Feed and Fuel from Biomass, Challal, D. S., IBH Publishing Co. Pvt. Ltd., 1991.
- 4. Biomass Conversion and Technology, C. Y. WereKo-Brobby and E. B. Hagan, John Wiley & Sons, 1996.

The break-up of CIE: Internal Tests + Assignments + Quizzes

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DEPARTMENT OF INFORMATION TECHNOLOGY

Fundamentals of Python Programming

(Open Elective)

SYLLABUS FOR M.E. / M.Tech. II – SEMESTER (Common to all Branches)

L:T:P(Hrs./week): 2:0:0	SEE Marks: 60	Course Code: P250E270XX
Credits: 3	CIE Marks: 40	Duration of SEE: 3 Hours

(OURSE OB	JECTIVES		COURSE OUTCOMES
2.	Acquire skills	problem	solving	On completion of the course, students will be able to
3.		grams using and use	, ,	 Develop Python programs with conditional statements and loops. Write programs using functions, strings and lists. Construct Python data structures programs using tuples, dictionaries and set. Write programs using Files and Class Concept . Try simple example using Python libraries NumPy, SciPy and Matplotlib

UNIT-I:

Basics of Python Programming: Features of Python, variables and identifiers, operators and expressions.

Decision control Statements: Selection/Conditional branching statements, basic loop structures/iterative Statements, nested loops, break, continue, and pass Statements.

Functions and Modules: function definition, function call, more on defining functions, recursive functions, modules.

UNIT-II:

Data Structures: Strings: Introduction, built-in string methods and functions, slice operation, String Module. Regular Expressions.

Lists: Introduction, nested list, cloning lists, basic list operations, list methods. Functional programming-filter(),map(),reduce() function.

UNIT -III:

Tuples: Introduction, basic tuple operations, tuple assignment, tuples for returning multiple values, nested tuples, tuple methods and functions.

Set: Introduction, Set operations.

Dictionaries: Basic operations, sorting items, looping over dictionary, nested dictionaries, built-in dictionary functions.

UNIT-IV:

Files and Exceptions: reading and writing files, pickling, handling exceptions. Built-in and user-defined exceptions.

OOPS Concepts: Introduction, classes and object, class method and self argument, theinit()method, class variables and object variables, public and private data members, Inheritance, Operator Overloading.

UNIT-V:

Python Libraries: NumPy – Introduction, Arrays – creation, operations, **SciPy**– Introduction, linalg, special, **Matplotlib** – Introduction, types of Plots, using pyplot.

Learning Resources:

- 1. Reema Thareja, "Python programming using problem solving approach", Oxford university press.
- 2. Allen Downey," Think Python: How to Think Like a Computer Scientist", O'Reilly publications, 2nd Edition.
- 3. Mark Lutz, "Learning Python", O'Reilly Publications.
- 4. Wesley J. Chun, "Core Python Programming", Prentice Hall, 2nd Edition.
- 5. http://www.python.org

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